

High Efficiency 8-CH LED Backlight Driver with Dual LCD Bias Power

Features

- Backlight LED Driver
 - ▶ Wide input range: 2.7V~5.5V
 - ▶ High efficiency step-up LED driver with 8-Ch current sinks, up to 40V boost voltage.
 - Up to 30mA/Ch or 32.4mA/Ch
 - $\pm 1.2\%$ current matching at 20mA
 - $\pm 2.2\%$ current accuracy at 20mA
 - ▶ I²C/PWM dual dimming control scheme
 - High resolution I²C 12-bit linear or Gamma 2.2 dimming
 - Wide range PWM dimming.
 - 100Hz to 100kHz frequency
 - 0.2% to 100% duty cycle at 20kHz
 - ▶ Programmable current sink turn on/off ramp time/shape and transition ramp up/down time.
 - ▶ 1.0MHz typical boost switching frequency
 - ▶ Programmable input PWM hysteresis to minimize jitter at low PWM duty cycle.
 - ▶ Programmable OVP and current limit
 - ▶ LED open/short protection
 - ▶ Optional external PMOS control to isolate boost output from input during shutdown
- LCD Panel Bias
 - ▶ Wide input range: 2.7V~5.5V
 - ▶ Programmable dual output Bias regulator using a single inductor.
 - ▶ Programmable ramp time for OUTP and OUTN
 - ▶ Charge pump PFM mode at light load
 - ▶ LCD Bias efficiency: up to 85%
 - ▶ Wide dual output voltage range $\pm 4.0\text{V}$ to $\pm 6.3\text{V}$ (50mV/step) and output current up to 300mA at $V_{IN} \geq 3.2\text{V}$ and $V_{HR_LCD}=0.5\text{V}$
 - ▶ Active output discharge function
 - ▶ Current limit and short protection
- Others
 - ▶ System level input UVLO
 - ▶ Thermal shutdown protection
 - ▶ Low shutdown current $<1\mu\text{A}$
 - ▶ Flexible I²C interface
 - ▶ Pb-free Packages:
 - ▶ WQFN55-32 (5mm x 5mm, 32 Lead)
 - ▶ RoHS and Green Compliant
 - ▶ -40°C to +85°C Temperature Range

Brief Description

KTZ8869 is the ideal power solution for LED backlighting and LCD bias power of medium size panels. It integrates two step-up converters for LED backlighting, a step-up converter with LDO and inverting charge pump for LCD bias power, resulting in a simpler and smaller solution with fewer external components. High switching frequency allows the use of smaller inductors and capacitors. Its input operating range is from 2.7V to 5.5V, accommodating 1-cell lithium-ion batteries or 5V supply.

The LED driver has two step-up converters, and each converter drive four current sinks with total eight current sinks. Each current sink can regulate up to 30mA/32.4mA with its maximum boost output voltage up to 40V. 12-bit linear or Gamma 2.2 I_{LED} resolution can be obtained over I²C or PWM dimming. For additional flexibility, PWM dimming offers wide range frequency and duty cycle to support Content Adaptive Brightness Control (CABC).

The LCD bias power section includes a step-up converter, LDO and an inverting charge pump to generate dual outputs, OUTP and OUTN, whose voltages can be programmed via an I²C interface. By integrating synchronous rectification MOSFETs for the step-up converter and charge pump, the KTZ8869 maximizes conversion efficiency up to 85%.

Various protection features are built into KTZ8869, including inductor current limit protection, output short circuit protection, output over-voltage protection, LED fault (open or short) protection and thermal shutdown protection.

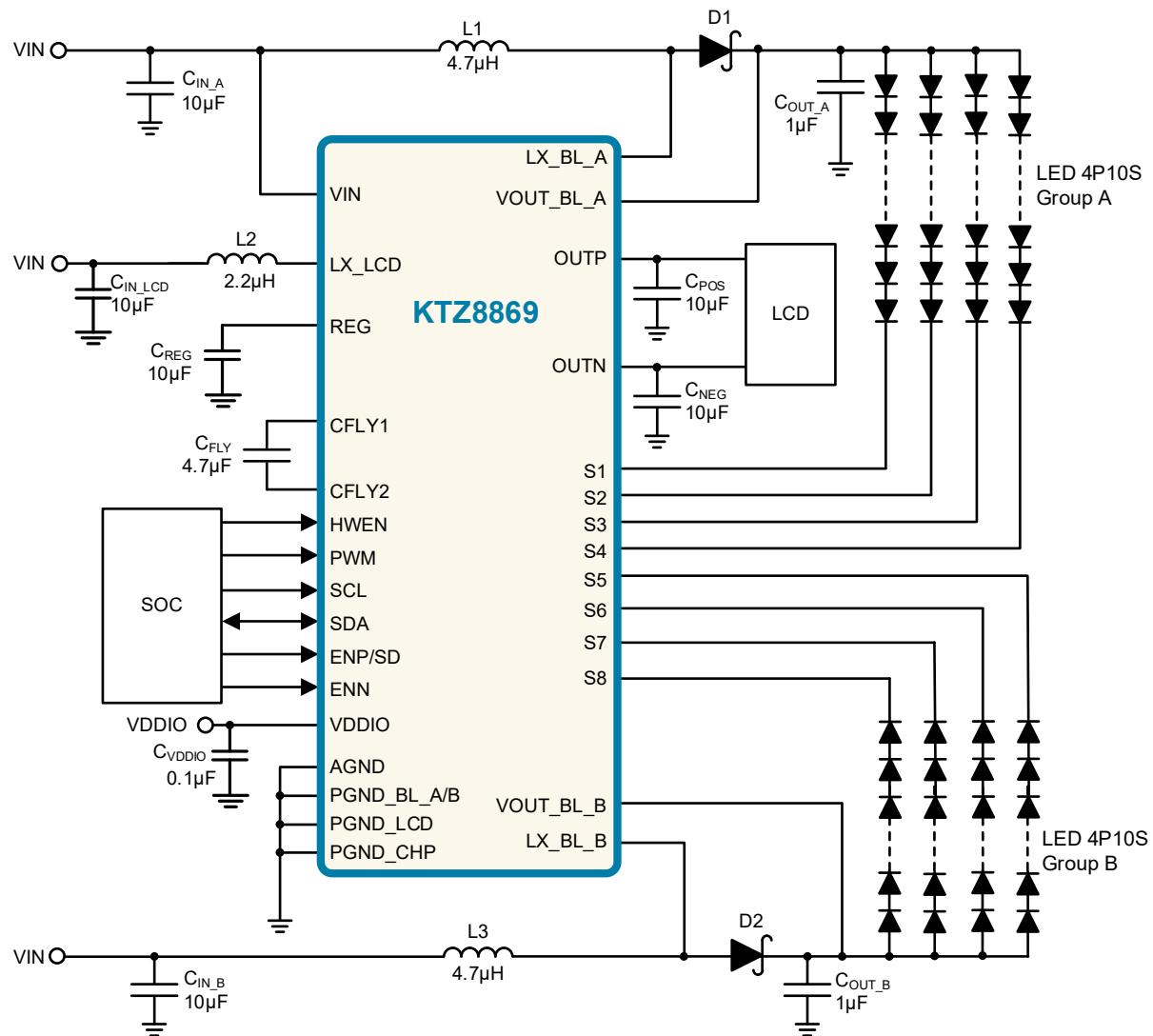
KTZ8869 is equipped with I²C interface for various controls and status monitor.

KTZ8869 is available in a RoHS and Green compliant WQFN55-32 (5mm x 5mm, 32 Lead).

Applications

- Tablet Backlight and Bias

Typical Application

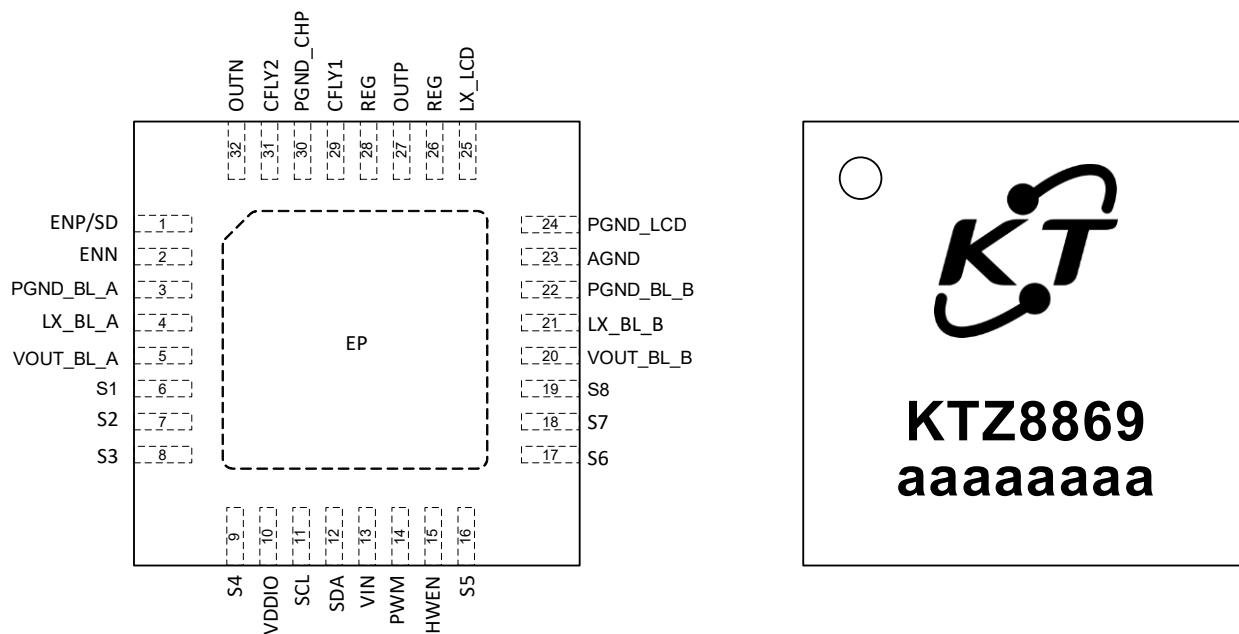


Ordering Information

Part Number	Marking ¹	Operating Temperature	Package
KTZ8869EUAD-TB	KTZ8869 aaaaaaaaaa	-40°C to +85°C	WQFN55-32

Pinout Diagram

WQFN55-32



Top View

32-Pin 5.00mm x 5.00mm x 0.75mm

WQFN Package

Top Mark

aaaaaaaaaa = Assembly Lot Tracking Number

1. aaaaaaaaaa = Assembly Lot Tracking Number.

Pin Descriptions

Pin #	Name	Function
1	ENP/SD	Dual-function pin selected by I ² C. For ENP input function, acts as enable pin for positive power (OUTP) with 300kΩ pull down resistor to GND. For SD output function, controls external PMOS to isolate backlight boost converters' outputs from input supply in shutdown condition.
2	ENN	Enable pin for negative power (OUTN), 300kΩ pull down resistor to GND.
3	PGND_BL_A	Power Ground for LED boost converter A.
4	LX_BL_A	Switching pin of the LED step-up converter A.
5	VOUT_BL_A	Output voltage sense pin of the step-up converter A.
6	S1	Regulated output current sink #1.
7	S2	Regulated output current sink #2.
8	S3	Regulated output current sink #3.
9	S4	Regulated output current sink #4.
10	VDDIO	Connected to system VDDIO with 0.1μF capacitor.
11	SCL	Clock of the I ² C interface.
12	SDA	Bi-directional data pin of the I ² C interface.
13	VIN	Input supply pin for the IC, bypass with a 10μF ceramic capacitor to GND.
14	PWM	PWM dimming input pin, 300kΩ pull-down resistor at this pin to GND.
15	HWEN	Active high hardware enable pin, 300kΩ pull-down resistor to GND.
16	S5	Regulated output current sink #5.
17	S6	Regulated output current sink #6.
18	S7	Regulated output current sink #7.
19	S8	Regulated output current sink #8.
20	VOUT_BL_B	Output voltage sense pin of the step-up converter B.
21	LX_BL_B	Switching pin of the LED step-up converter B.
22	PGND_BL_B	Power Ground for LED boost converter B.
23	AGND	Analog ground pin.
24	PGND_LCD	Power ground for LCD Bias power supply boost converter.
25	LX_LCD	Switching node of the LCD Bias boost converter.
26, 28	REG	LCD-Bias Boost converter output pin, bypass a 10μF ceramic capacitor to PGND_LCD.
27	OUTP	LDO output pin of the positive power, bypass with a 10μF ceramic capacitor.
29	CFLY1	Negative charge pump flying capacitor pin positive connection.
30	PGND_CHP	Power ground for negative charge pump.
31	CFLY2	Negative charge pump flying capacitor negative connection.
32	OUTN	Charge pump output pin of the negative power. Bypass with a 10μF ceramic capacitor to PGND_CHP.
EP	Exposed Pad	Thermal pad of the package. Must be soldered to achieve appropriate dissipation. Must be connected to GND for proper function.

Absolute Maximum Ratings²

Symbol	Description	Value	Units
VIN	Input Voltage	-0.3 to 6	V
LX_BL_A, LX_BL_B	LX_BL to GND DC	-0.3 to 42	V
	LX_BL to GND AC Transient: 100ns	-1.0 to 44	V
VOUT_A, VOUT_B	LED Backlight driver output node	-0.3 to 42	V
S1, S2, S3, S4, S5, S6, S7, S8	LED Backlight driver current sink	-0.3 to 32	V
HWEN, SCL, SDA, PWM, ENP/SD, ENN, VDDIO	Control Pins	-0.3 to VIN+0.3	V
LX_LCD, CFLY1, OUTP, REG	LCD Bias power positive voltage and switching node DC	-0.3 to 7	V
LX_LCD	LCD Bias switching node AC Transient: 200ns	-1.0 to 8	V
OUTN, CFLY2	LCD Bias power negative output voltage and switching node	-7 to 0.3	V
T _J	Junction Operating Temperature Range	-40 to 150	°C
T _S	Storage Temperature Range	-65 to 150	°C
T _{LEAD}	Maximum Soldering Temperature (at leads, 10 sec)	300	°C
ESD	HBM Electrical Static Discharge	2.0	kV

ESD and Surge Ratings

Symbol	Description	Value	Units
VESD	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001	±2000	V
	Charge device model (CDM), per JEDEC specification JESD22-C101	±500	V

Thermal Capabilities³

Symbol	Description	Value	Units
Θ _{JA}	Thermal Resistance – Junction to Ambient	29.1	°C/W
P _D	Maximum Power Dissipation at T _A ≤ 25°C	4.3	W
ΔP _D /ΔT	Derating Factor Above T _A = 25°C	-34.4	mW/°C

2. Stresses above those listed in Absolute Maximum Ratings may cause permanent damage to the device. Functional operation at conditions other than the operating conditions specified is not implied. Only one Absolute Maximum rating should be applied at any one time.

3. Junction to Ambient thermal resistance is highly dependent on PCB layout. Values are based on thermal properties of the device when soldered to an EV board.

Electrical Characteristics⁴

Unless otherwise noted, the *Min* and *Max* specs are applied over the full operation temperature range of -40°C to $+85^{\circ}\text{C}$, while *Typ* values are specified at room temperature (25°C). $V_{IN} = 3.6\text{V}$.

IC Supply

Symbol	Description	Conditions	Min	Typ	Max	Units
V_{IN}	Input operating range		2.7		5.5	V
UVLO	Input under voltage lockout	Rising edge		2.43	2.65	V
		Falling edge		2.3	2.49	V
$UVLO_{HYST}$	UVLO hysteresis			0.13		V
I_Q	IC standby current	HWEN = VDDIO, LCD Boost disabled, LED Boost and Current Sink disabled.		1.0	5.0	μA
I_{LCD_EN}	Bias power no load current	LED Boost and Current Sink disabled. OUTP, OUTN enabled with no load.		1.0	1.5	mA
I_{SHDN}	IC shutdown V_{IN} current	HWEN = 0, ENP = ENN = GND		1.0	3.0	μA

Boost Converter A/B for LED Backlight

Symbol	Description	Conditions	Min	Typ	Max	Units
$R_{DS(ON)}$	NMOS on-resistance	$V_{IN} = 3.6\text{V}$, $I_{SW} = 250\text{mA}$, $T_A = 25^{\circ}\text{C}$	100	180	300	$\text{m}\Omega$
I_{LIM}	Peak NMOS current limit	Reg 0x11[1:0]=00, $T_A = 25^{\circ}\text{C}$	1.02	1.2	1.38	A
F_{SW}	Oscillator frequency	$T_A = 25^{\circ}\text{C}$	0.9	1.0	1.1	MHz
EFF_{LEDBST}	Boost Efficiency ⁵	$V_{IN} = 3.6\text{V}$, $I_{LED} = 5\text{mA}/\text{ch}$, 8P6S LEDs, Typical application circuit.		87		%
D_{MAX}	Maximum duty cycle ⁵	$F_{SW} = 1\text{MHz}$, $T_A = 25^{\circ}\text{C}$	91	94		%
V_{OVP}	OVP threshold	Reg 0x02[7:5]=111, default, $T_A = 25^{\circ}\text{C}$	38.5	40	41.3	V
	OVP hysteresis			2		V
R_{SD}	SD pin internal pulldown resistance		23	33	43	$\text{k}\Omega$

Current Sink for LED Backlight

Symbol	Description	Conditions	Min	Typ	Max	Units
I_{SINK_ACC}	Output current accuracy	Current setting = 30mA, $T_A = 25^{\circ}\text{C}$	-2.0		2.0	%
		Current setting = 20mA, $T_A = 25^{\circ}\text{C}$	-2.2		2.2	%
		Current setting = 1mA, $T_A = 25^{\circ}\text{C}$	-3.0		3.0	%
I_{SINK_MATCH}	Output current matching ⁶	Current setting = 30mA, $T_A = 25^{\circ}\text{C}$	-1.0		1.0	%
		Current setting = 20mA, $T_A = 25^{\circ}\text{C}$	-1.2		1.2	%
		Current setting = 1mA, $T_A = 25^{\circ}\text{C}$	-2.5		2.5	%
V_{HR}	Current sink head room voltage		0.35	0.45	0.7	V
I_{LED_MIN}	Minimum LED current per string	Gamma 2.2 mapping, $I_{LED_FS}=30\text{mA}$		50		μA
I_{STEP}	LED current step size ⁵	Linear mapping, $I_{LED_FS}=30\text{mA}$		7.32		μA
V_{SOV}	Current sink over voltage threshold ⁵		5.25	6	7	V
T_{FAULT}	Current sink fault delay		50	60	70	ms

(continued next page)

4. KTZ8869 is guaranteed to meet performance specifications over the -40°C to $+85^{\circ}\text{C}$ operating temperature range by design, characterization, and correlation with statistical process controls.

5. Guarantee by characterization and/or simulation.

6. The current matching among channels is defined as $|I_{SINK_AVG}|_{MAX}/I_{AVG}$.

Electrical Characteristics (continued)⁷

Unless otherwise noted, the *Min* and *Max* specs are applied over the full operation temperature range of -40°C to $+85^{\circ}\text{C}$, while *Typ* values are specified at room temperature (25°C). $V_{\text{IN}} = 3.6\text{V}$.

Boost Converter for LCD Power Bias

Symbol	Description	Conditions	Min	Typ	Max	Units
V_{REG}	LCD boost output voltage range		4		6.6	V
	LCD boost output voltage step size ⁸			50		mV
$I_{\text{REG_LIM}}$	Peak current limit	$V_{\text{IN}} = 3.6\text{V}, T_A = 25^{\circ}\text{C}$	1.9	2.2	2.9	A
F_{SW}	Oscillator frequency	Continuous Mode, $T_A = 25^{\circ}\text{C}$	1.8	2.0	2.2	MHz
$\text{EFF}_{\text{LCDBST}}$	Efficiency ⁸	$V_{\text{IN}} = 3.6\text{ V}, V_{\text{REG_OUT}} = 5.9\text{ V}, 6\text{mA} < I_{\text{O}} < 400\text{mA}$, Typical application circuit		85		%
$R_{\text{ON_HS}}$	High side FET on resistance	$V_{\text{IN}} = 3.6\text{V}, T_A = 25^{\circ}\text{C}$		220	280	$\text{m}\Omega$
$R_{\text{ON_LS}}$	Low side FET on resistance	$V_{\text{IN}} = 3.6\text{V}, T_A = 25^{\circ}\text{C}$		200	250	$\text{m}\Omega$
$V_{\text{REG_PP}}$	LCD boost output ripple ⁸	$I_{\text{O}} = 5\text{mA}$ and 250mA , $C_{\text{O}} = 10\mu\text{F}$		50		mV_{PP}
D_{MAX}	Maximum duty cycle		85	90		%

OUTP-Positive Output

Symbol	Description	Conditions	Min	Typ	Max	Units
OUTP	Positive output voltage range		4.0		6.3	V
	Output voltage step size ⁸			50		mV
	Output voltage accuracy	$V_{\text{OUTP}} = 5.5\text{V}$, no load	-1.5		+1.5	%
$I_{\text{OUTP_MAX}}$	Maximum output current	$V_{\text{IN}} \geq 3.2\text{V}, V_{\text{HR_LCD}} = 0.5\text{V}$	300			mA
$I_{\text{OUTP_LIM}}$	Positive output current limit	$V_{\text{IN}} = 3.6\text{V}, V_{\text{REG}} = 6.0\text{V}, V_{\text{OUTP}} = 5.5\text{V}, T_A = 25^{\circ}\text{C}$	310	380	430	mA
$V_{\text{OUTP_LOREG}}$	VOUTP LDO load regulation ⁸	$0 \leq I_{\text{O}} \leq I_{\text{OUTP_MAX}}$			80	mV
$V_{\text{OUTP_DO}}$	VOUTP LDO dropout voltage ⁸	$I_{\text{OUTP}} = I_{\text{OUTP_MAX}}, V_{\text{OUTP}} = 5.5\text{V}$			500	mV
$T_{\text{OUTP_SS}}$	Startup time	$C_{\text{O}} = 10\mu\text{F}, V_{\text{OUTP}} = 5.75\text{V}, V_{\text{OUTP_RAMP}} = 2\text{b}'01$		456		μs
$R_{\text{PD_OUTP}}$	Output pulldown resistor in shutdown		40	70	100	Ω

OUTN-Negative Output

Symbol	Description	Conditions	Min	Typ	Max	Units
OUTN	Negative output voltage range		-6.3		-4.0	V
	Output voltage step size ⁸			50		mV
	Output voltage accuracy	$V_{\text{OUTN}} = -5.4\text{V}$, no load	-1.5		+1.5	%
$I_{\text{OUTN_MAX}}$	Maximum output current limit	$V_{\text{IN}} \geq 3.2\text{V}, V_{\text{HR_LCD}} = 0.5\text{V}$	300			mA
EFF_{CHP}	Inverting charge pump efficiency ⁸	$V_{\text{REG}} = 5.7\text{V}, V_{\text{OUTN}} = -5.4\text{V}, I_{\text{OUTN}} > -5\text{mA}$		85		%
$T_{\text{OUTN_SS}}$	Startup time	$C_{\text{O}} = 10\mu\text{F}, V_{\text{OUTN}} = -5.75\text{V}, V_{\text{OUTN_RAMP}} = 4\text{b}'0001$		912		μs
$R_{\text{PD_OUTN}}$	Output pulldown resistor in shutdown			20	35	Ω

(continued next page)

7. KTZ8868 is guaranteed to meet performance specifications over the -40°C to $+85^{\circ}\text{C}$ operating temperature range by design, characterization, and correlation with statistical process controls.

8. Guarantee by characterization and/or simulation.

Electrical Characteristics (continued)⁹

Unless otherwise noted, the *Min* and *Max* specs are applied over the full operation temperature range of -40°C to $+85^{\circ}\text{C}$, while *Typ* values are specified at room temperature (25°C). $V_{\text{IN}} = 3.6\text{V}$.

PWM INPUT¹⁰

Symbol	Description	Conditions	Min	Typ	Max	Units
$f_{\text{PWM_INPUT}}$	PWM input frequency		0.1		100	kHz
$t_{\text{MIN_ON}}$	Minimum pulse ON time			150		ns
$t_{\text{MIN_OFF}}$	Minimum pulse OFF time			150		ns
PWM_{RES}	PWM input resolution	$100\text{Hz} < f_{\text{PWM}} < 10\text{KHz}$		11		bit

I²C-Compatible Voltage Specifications (SCL, SDA, ENP, ENN, PWM, HWEN, VDDIO)

Symbol	Description	Conditions	Min	Typ	Max	Units
VDDIO	VDDIO input voltage range		1.0		$V_{\text{IN}} + 0.3$	V
V_{IL}	Input Logic Low Threshold				0.35^* VDDIO	
V_{IH}	Input Logic High Threshold		0.65^* VDDIO			V
V_{OL}	SDA Output Logic Low	$I_{\text{SDA}} = 2\text{mA}$			0.3	V
RPD _{HWEN}	Pulldown resistance on HWEN pin			300		$\text{k}\Omega$
RPD _{PWM}	Pulldown resistance on PWM pin			300		$\text{k}\Omega$
RPD _{ENP}	Pulldown resistance on ENP pin			300		$\text{k}\Omega$
RPD _{ENN}	Pulldown resistance on ENN pin			300		$\text{k}\Omega$

I²C-Compatible Timing Specifications (SCL, SDA), see Figure 1¹⁰

Symbol	Description	Conditions	Min	Typ	Max	Units
$t_{\text{LOW_SCL}}$	SCL low clock period		1.25			μs
$t_{\text{HIGH_SCL}}$	SCL high clock period		0.65			μs
f_{SCL}	SCL clock frequency				400	kHz
$t_{\text{SU_DAT}}$	Data in setup time to SCL high		100			ns
$t_{\text{V_DAT}}$	Data valid time				0.9	μs
$t_{\text{HD_DAT}}$	Data out stable after SCL low		0			ns
t_{START}	SDA low setup time to SCL low (Start)		100			ns
t_{STOP}	SDA high hold time after SCL high (Stop)		100			ns
t_{RISE}	SDA/SCL rise time	$V_{\text{PULLUP}} = 1.8\text{V}$, $R_{\text{PULLUP}} = 1\text{k}\Omega$, $C_{\text{BUS}} = 100\text{pF}$			300	ns
t_{FALL}	SDA/SCL fall time	$V_{\text{PULLUP}} = 1.8\text{V}$, $R_{\text{PULLUP}} = 1\text{k}\Omega$, $C_{\text{BUS}} = 100\text{pF}$			300	ns

Thermal Shutdown¹⁰

Symbol	Description	Conditions	Min	Typ	Max	Units
$T_{\text{J-TH}}$	IC thermal shutdown threshold			150		$^{\circ}\text{C}$
	IC thermal shutdown hysteresis			15		$^{\circ}\text{C}$

9. KTZ8869 is guaranteed to meet performance specifications over the -40°C to $+85^{\circ}\text{C}$ operating temperature range by design, characterization, and correlation with statistical process controls.

10. Guarantee by characterization and/or simulation.

Timing Diagrams

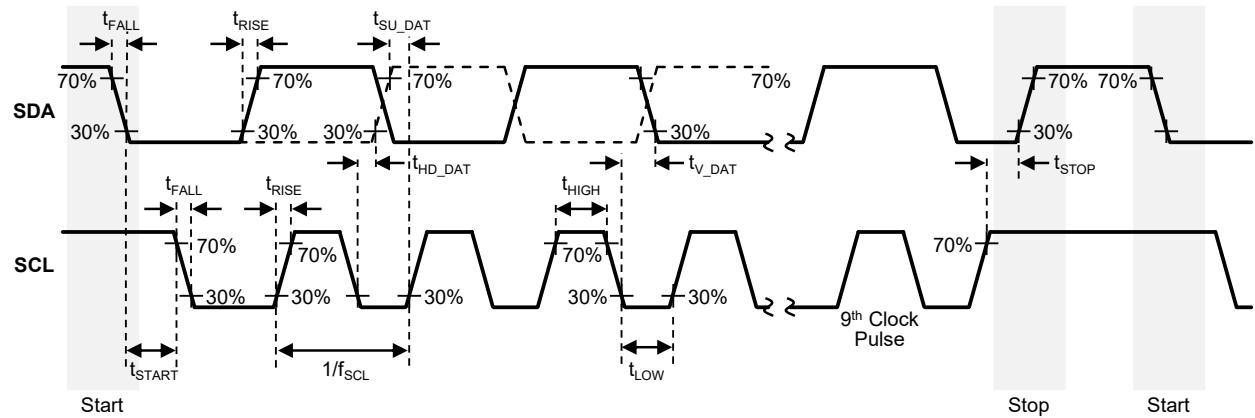


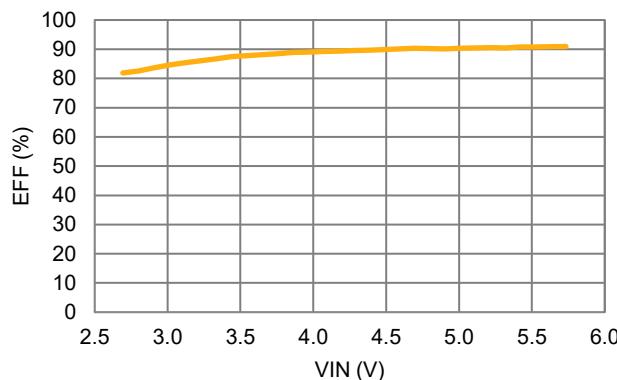
Figure 1. I²C Compatible Interface Timing

Typical Characteristics

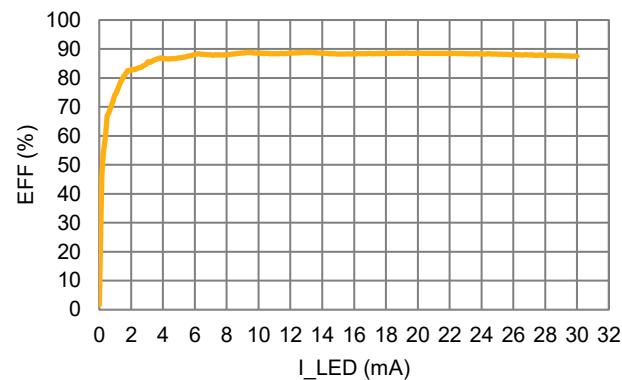
LED Backlight

$V_{IN} = 3.6V$, 8P6S LEDs, $I_{LED} = 30mA$, $L = VLF504012MT-4R7M-CA$, $C_{IN} = 10\mu F$, $C_{OUT} = 1\mu F$, I²C register default settings, Temp = 25°C unless otherwise specified.

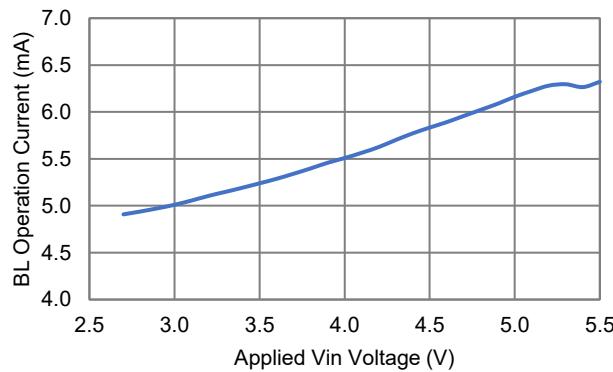
LED Driver Efficiency vs. VIN



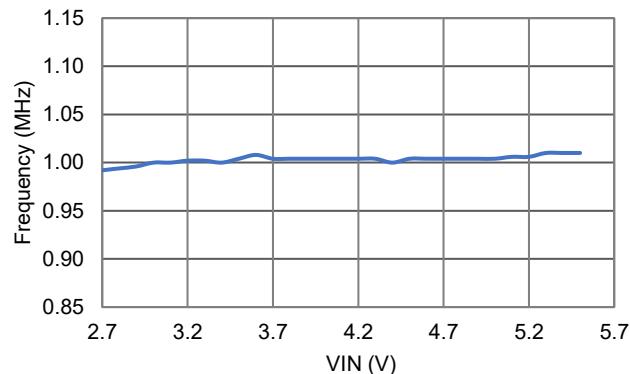
LED Driver Efficiency vs. I_LED



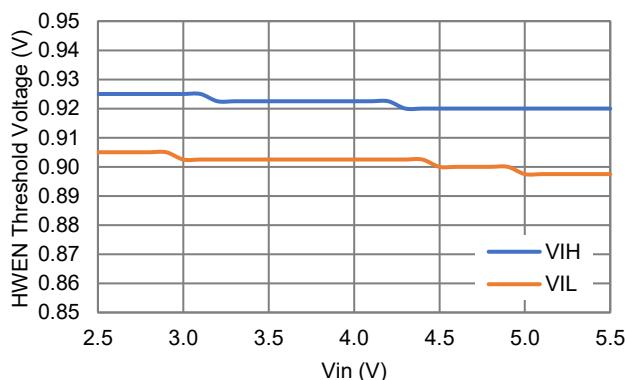
Operating Current vs. VIN



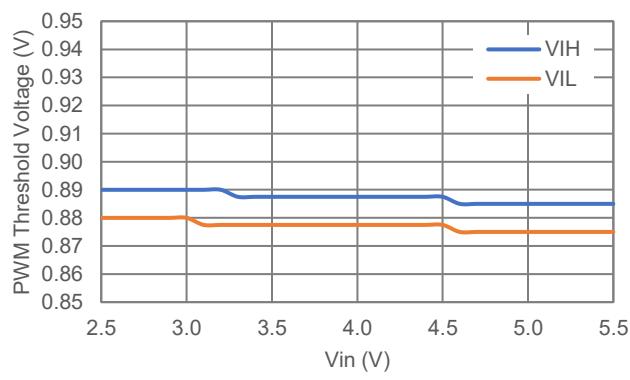
Switching Frequency vs. VIN



HWEN Logic Threshold Voltage
($V_{IN} = 2.5V$ to $5.5V$, $V_{DDIO} = 1.8V$)



PWM Logic Threshold Voltage
($V_{IN} = 2.5V$ to $5.5V$, $V_{DDIO} = 1.8V$)



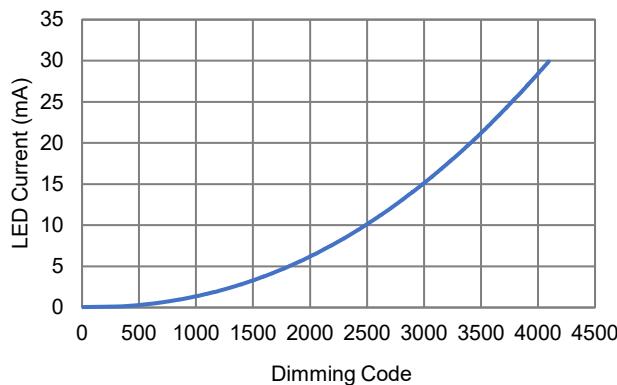
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Typical Characteristics

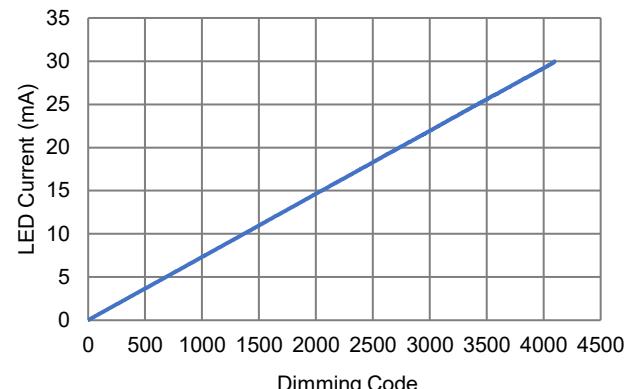
LED Backlight

$V_{IN} = 3.6V$, 8P6S LEDs, $I_{LED} = 30mA$, $L = VLF504012MT-4R7M-CA$, $C_{IN} = 10\mu F$, $C_{OUT} = 1\mu F$, I^2C register default settings, Temp = $25^{\circ}C$ unless otherwise specified.

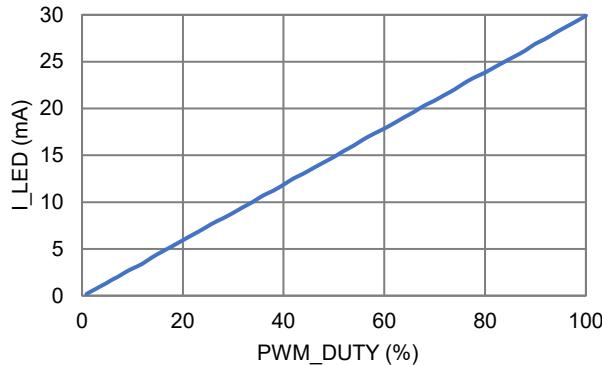
LED Current vs. Current Ratio Code
(12 bits, Gamma 2.2 Mapping)



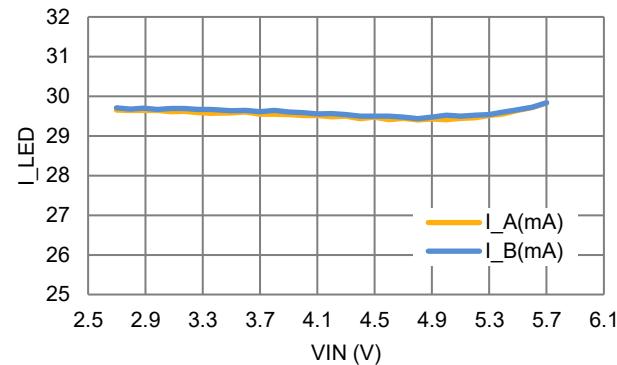
LED Current vs. Current Ratio Code
(12 bits, Linear Mapping)



LED Current vs. PWM Duty Cycle
(20 KHz)



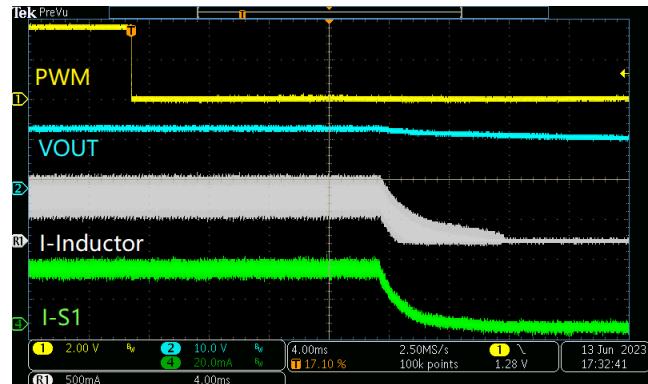
LED Current Line Regulation



Turn On by PWM
(Exponential)



Turn Off by PWM
(Exponential)

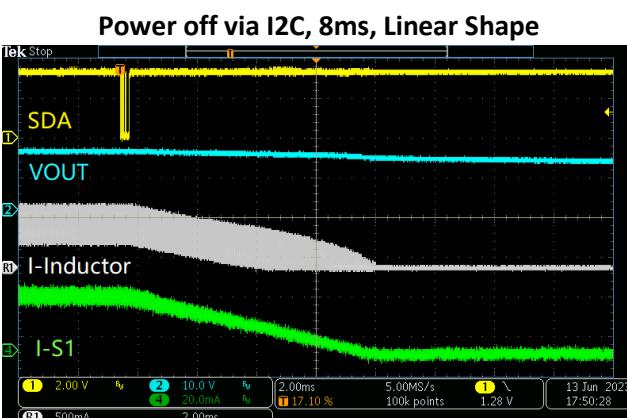
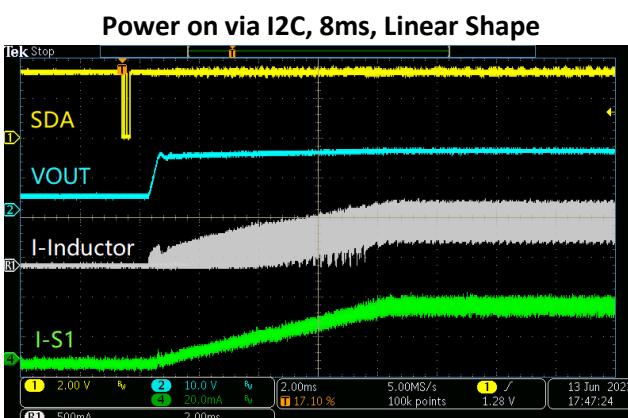
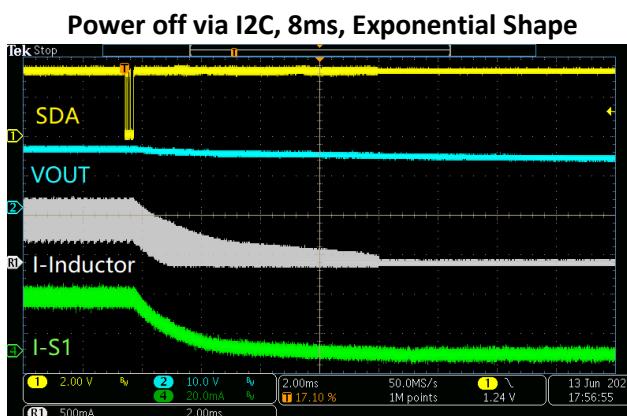
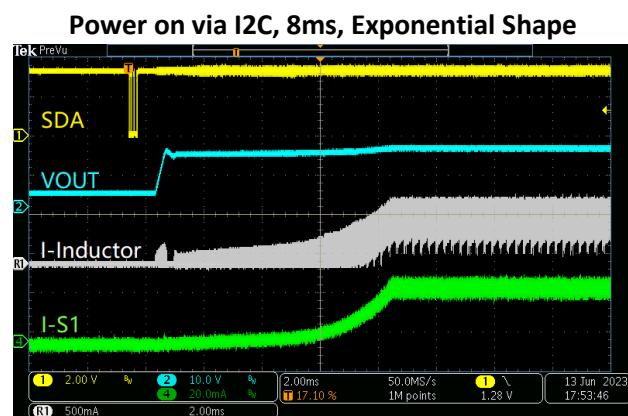
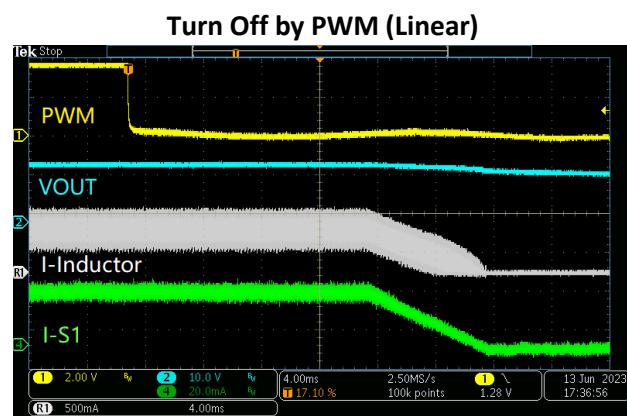
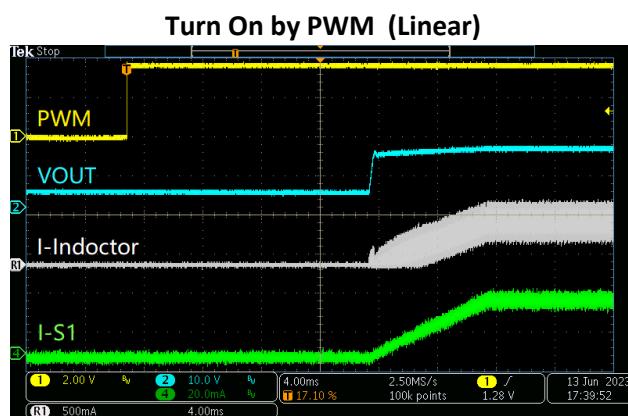


(continued next page)

Typical Characteristics (continued)

LED Backlight

$V_{IN} = 3.6V$, 8P6S LEDs, $I_{LED} = 30mA$, $L = VLF504012MT-4R7M-CA$, $C_{IN} = 10\mu F$, $C_{OUT} = 1\mu F$, I²C register default settings, Temp = 25°C unless otherwise specified.



(continued next page)

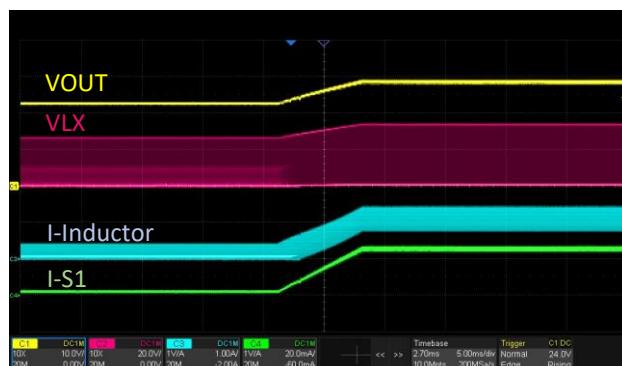
Typical Characteristics (continued)

LED Backlight

$V_{IN} = 3.6V$, 8P6S LEDs, $I_{LED} = 30mA$, $L = VLF504012MT-4R7M-CA$, $C_{IN} = 10\mu F$, $C_{OUT} = 1\mu F$, I^2C register default settings, Temp = $25^{\circ}C$ unless otherwise specified.

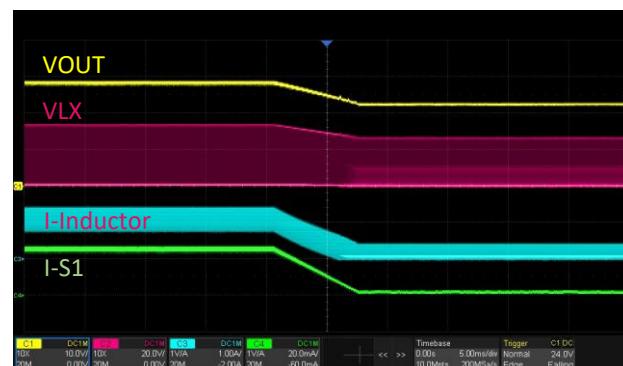
Ramp Up Waveform

I_{CH} from 3mA to 27mA, Linear Mapping

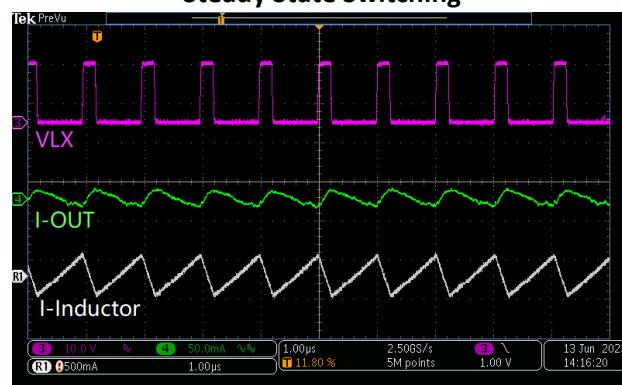


Ramp Down Waveform

I_{CH} from 27mA to 3mA, Linear Mapping



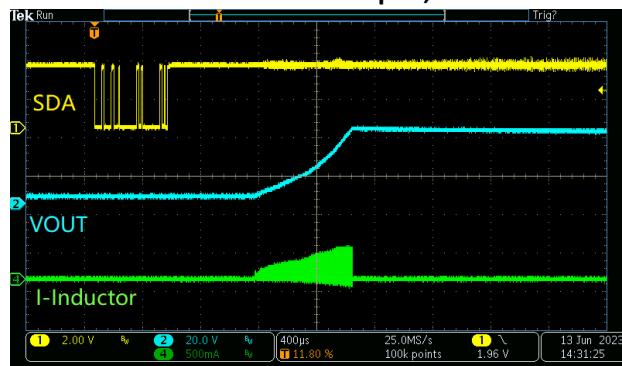
Steady State Switching



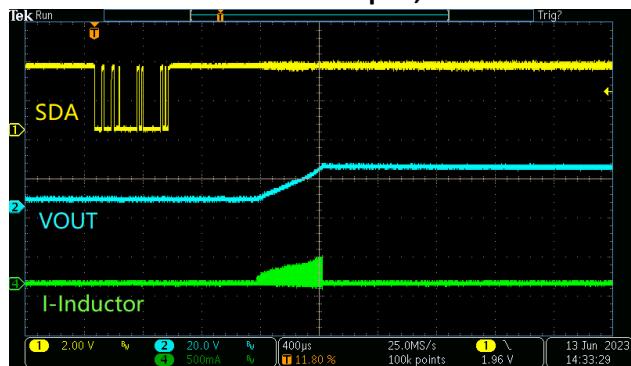
PWM Dimming



Power on with VOUT Open, 40V OVP



Power on with VOUT Open, 21.4V OVP



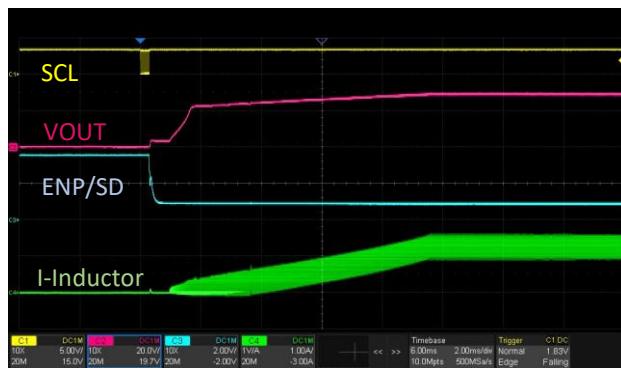
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Typical Characteristics (continued)

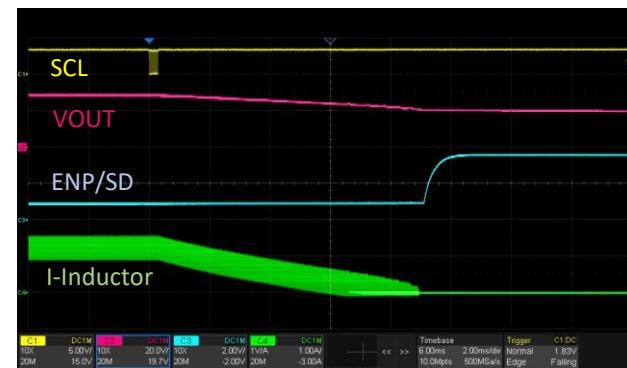
LED Backlight

$V_{IN} = 3.6V$, 8P6S LEDs, $I_{LED} = 30mA$, $L = VLF504012MT-4R7M-CA$, $C_{IN} = 10\mu F$, $C_{OUT} = 1\mu F$, I^2C register default settings, Temp = $25^{\circ}C$ unless otherwise specified.

Turning On with External PMOS



Turning Off with External PMOS



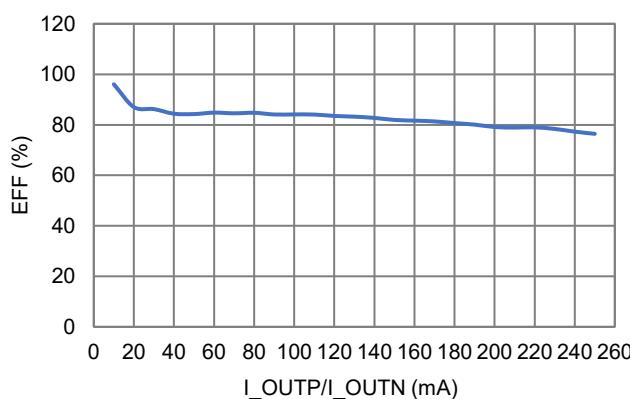
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Typical Characteristics (continued)

LCD Bias

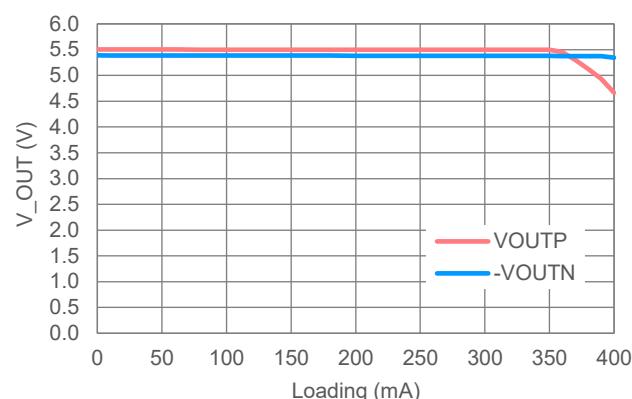
$V_{IN} = 3.6V$, $L = 2.2\mu H$ (TOKO DFE201612P-2R2M=P2), $C_{IN} = C_{REG} = C_{POS} = C_{NEG} = 10\mu F$, $C_{FLY} = 4.7\mu F$, $T_A = 25^\circ C$, unless otherwise specified. Default setting $V_{OUTP} = 5.5V$, $V_{OUTN} = -5.4V$, $V_{REG} = 5.8V$.

Efficiency vs. Output Current



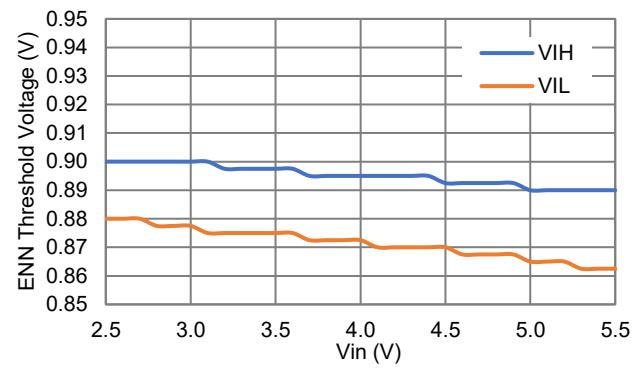
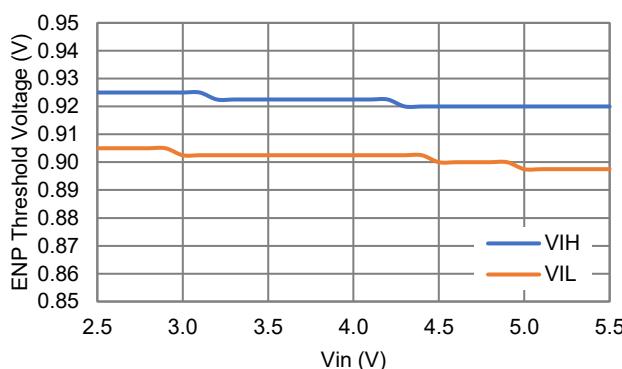
Bias V_OUT vs. Loading

($V_{IN} = 3.6V$, $V_{REG} = 6.0V$, $V_{OUTP} = +5.5V$, $V_{OUTN} = -5.4V$)

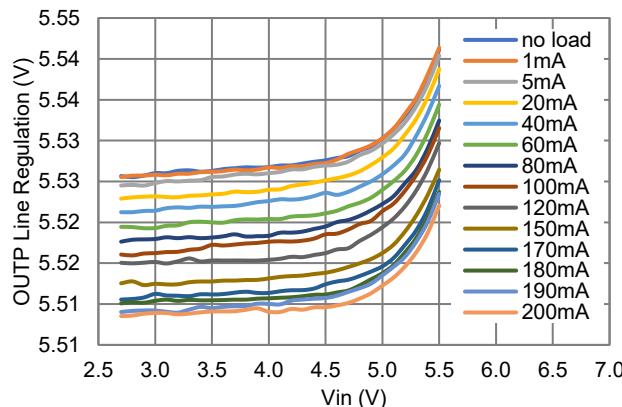


ENP/ENN Threshold vs. VIN

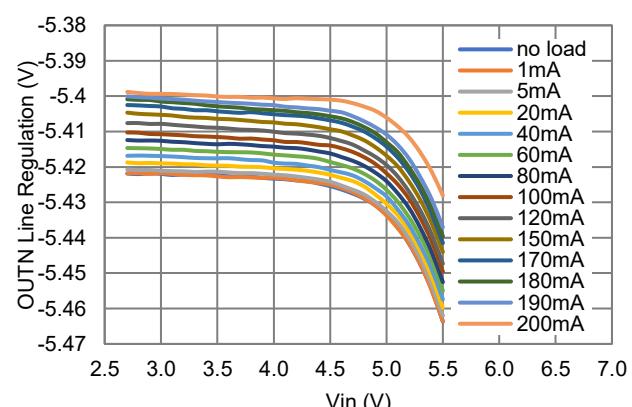
($V_{IN} = 2.5V$ to $5.5V$, $V_{DDIO} = 1.8V$)



OUTP Line Regulation



OUTN Line Regulation



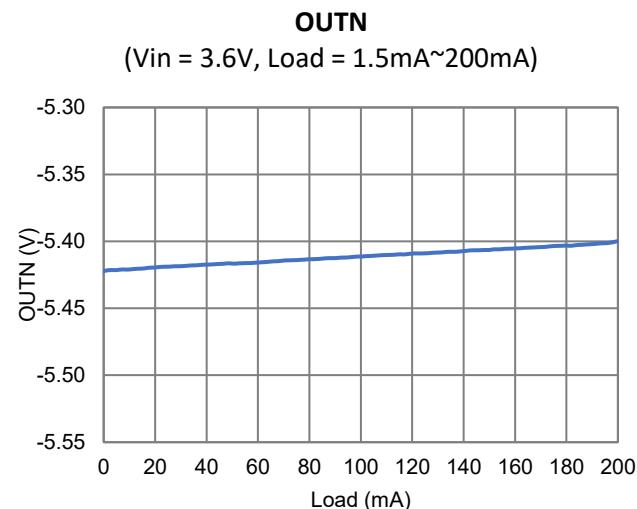
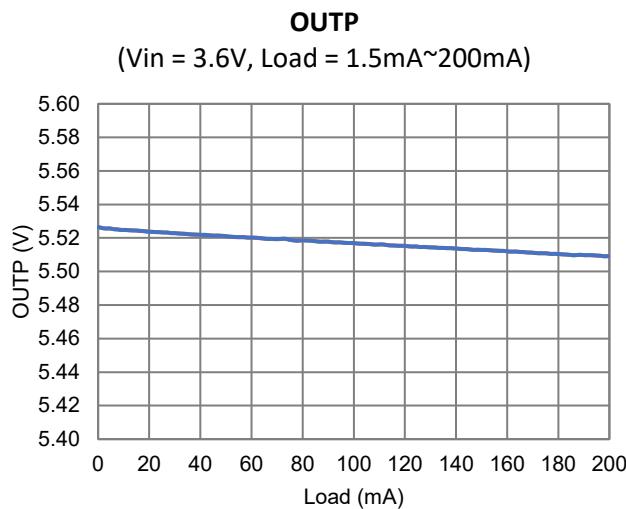
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Typical Characteristics (continued)

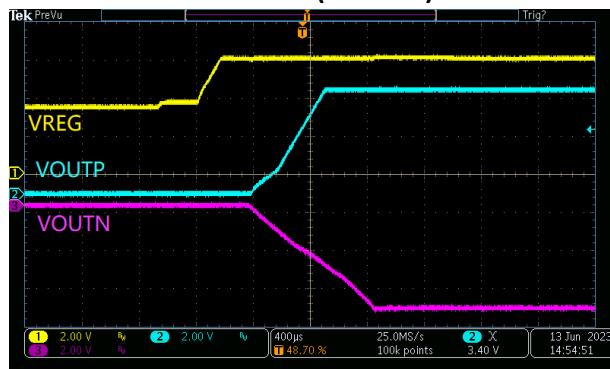
LCD Bias

$V_{IN} = 3.6V$, $L = 2.2\mu H$ (TOKO DFE201612P-2R2M=P2), $C_{IN} = C_{REG} = C_{POS} = C_{NEG} = 10\mu F$, $C_{FLY} = 4.7\mu F$, $T_A = 25^\circ C$, unless otherwise specified. Default setting $V_{OUTP} = 5.5V$, $V_{OUTN} = -5.4V$, $V_{REG} = 5.8V$.

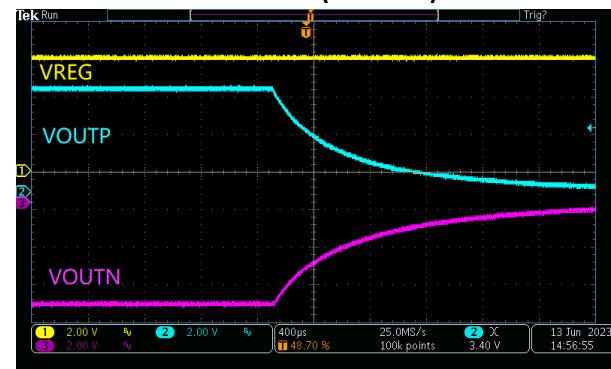
Load Regulation



Power on (No Load)



Power off (No Load)



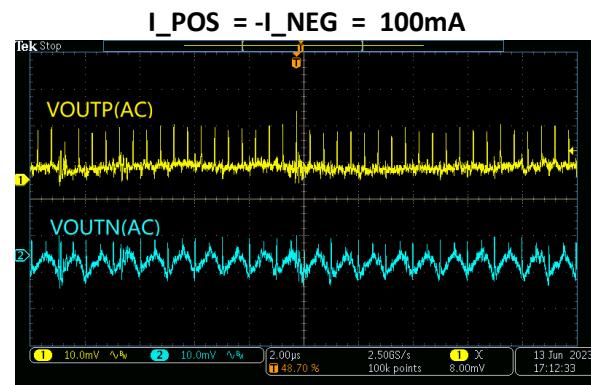
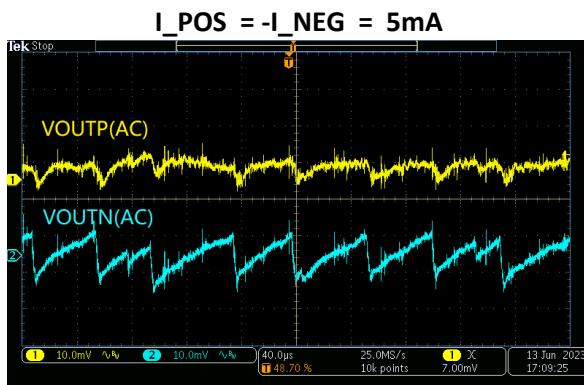
(continued next page)

Typical Characteristics (continued)

LCD Bias

$V_{IN} = 3.6V$, $L = 2.2\mu H$ (TOKO DFE201612P-2R2M=P2), $C_{IN} = C_{REG} = C_{POS} = C_{NEG} = 10\mu F$, $C_{FLY} = 4.7\mu F$, $T_A = 25^\circ C$, unless otherwise specified. Default setting $V_{OUTP} = 5.5V$, $V_{OUTN} = -5.4V$, $V_{REG} = 5.8V$.

Steady State Waveforms (PWM PFM)

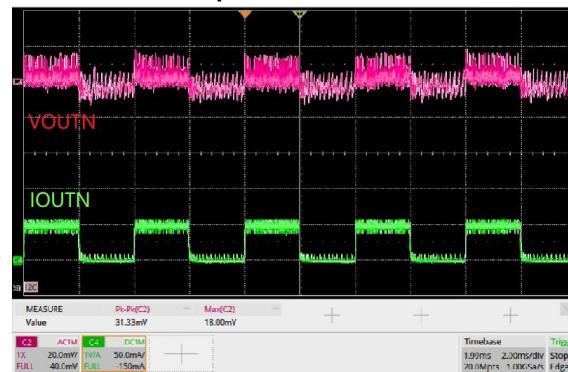


Load Transient

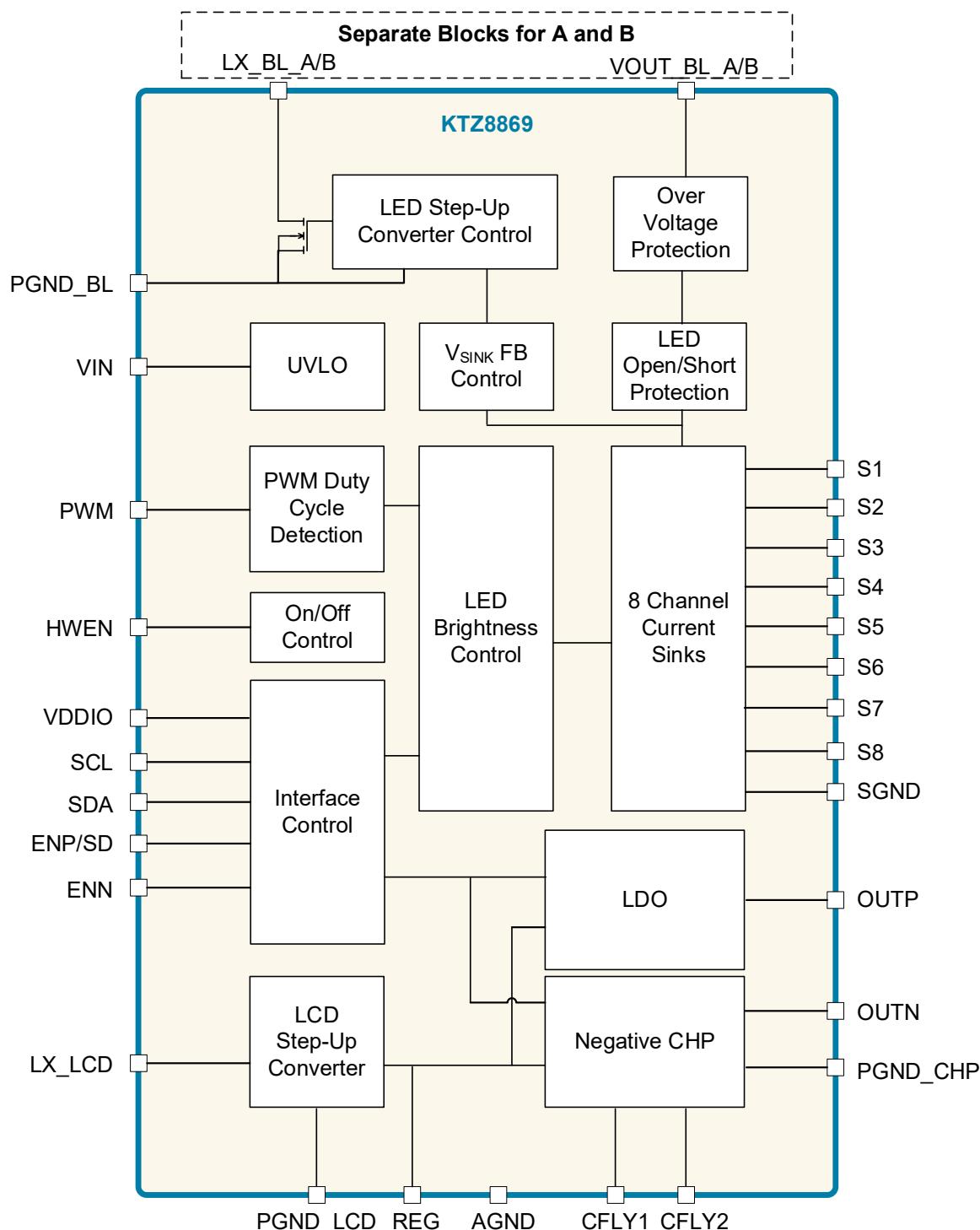
Step 0mA to 80mA



Step 0mA to 50mA



Functional Block Diagram



Functional Description

Overview

KTZ8869 is the ideal power solution for LED backlighting and LCD bias power of small and medium size panels. It integrates two step-up converters for LED backlighting, a step-up converter with LDO and inverting charge pump for LCD bias power, resulting in a simpler and smaller solution with fewer external components. High switching frequency allows the use of smaller inductors and capacitors. Its operating input ranges from 2.7V to 5.5V, accommodating 1-cell lithium-ion batteries or 5V supply.

The LED driver has two step-up converters, and each converter drivers four current sinks with total eight current sinks. Each regulated current sinks can regulate up to 30mA/32.4mA in backlight mode with its maximum boost output voltage up to 40V. 12-bit linear or Gamma 2.2 I_{LED} resolution can be obtained over I²C or PWM diming. For additional flexibility, PWM dimming offers wide range frequency and duty cycle to support Content Adaptive Brightness Control (CABC).

The LCD bias power includes a step-up converter, LDO and an inverting charge pump to generate dual outputs, OUTP and OUTN, whose voltages can be programmed via an I²C interface. By integrating synchronous rectification MOSFETs for the step-up converter and charge pump, the KTZ8869 maximizes conversion efficiency up to 85%.

Various protection features are built into KTZ8869, including inductor current limit protection, output short circuit protection, output over-voltage protection, LED fault (open or short) protection and thermal shutdown protection. KTZ8869 is equipped with I²C interface for various controls and status monitor.

Hardware Enable & Standby Mode

KTZ8869 has a logic input HWEN pin to enable/disable the device. When HWEN is set low, the device goes into shutdown mode, all I²C registers are reset to default, and the I²C interface is disabled. Under this condition, the device does not respond to any I²C command. Even when SCL/SDA's pull up voltage is much less than VIN voltage, it will not cause any extra leakage current.

When HWEN is set high, the device goes into standby mode, the I²C interface is enabled, and the device can respond to I²C command.

Either HWEN input or I²C command can be used to turn off the part, but there are some differences.

- If setting HWEN input low to turn off the part, the I_{LED} will be turned off immediately without any ramp down control. After that, the I²C interface is disabled.
- If using an I²C command to turn off backlight while keeping HWEN high, the I_{LED} will have ramp down control. After the LED current ramp down is finished, the I²C interface is still alive waiting for new command.

VDDIO

KTZ8869 has VDDIO pin. By Connecting to system VDDIO with 0.1 μ F capacitor, the KTZ8869 can identify the IO voltage level automatically.

Backlight Boost

Two step-up converters are used to generate high voltage for driving LED strings. An adaptive control method automatically adjusts output voltage by monitoring the headroom voltage of current sinks. In this way, KTZ8869 can offer much better efficiency. The switching frequency of KTZ8869 Backlight Boost is typical 1.0MHz.

Backlight Current Sink Setting

Each current sink can be enabled or disabled by register 0x08 bits [7:0]. They can be enabled by writing the backlight enable bit to HIGH in register 0x01 bit [0] after correctly setting of LED configuration and brightness. If

a current sink is not used, connect its output to GND. During the startup, KTZ8869 will automatically detect and disable the corresponding channel.

When PWM dimming is enabled and a non-zero PWM duty cycle is detected, the KTZ8869 multiplies the duty cycle with I²C brightness settings. Figure 2 and Figure 3 describe the start-up timing for operation with I²C controlled current and with PWM controlled current.

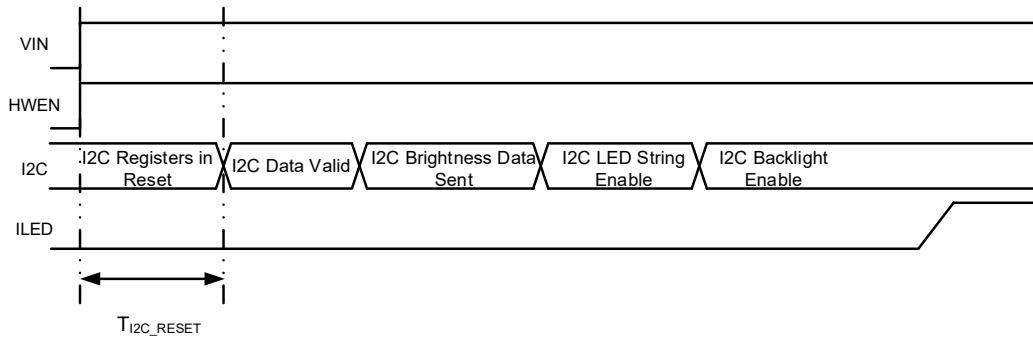


Figure 2. Enable of KTZ8869 via I²C

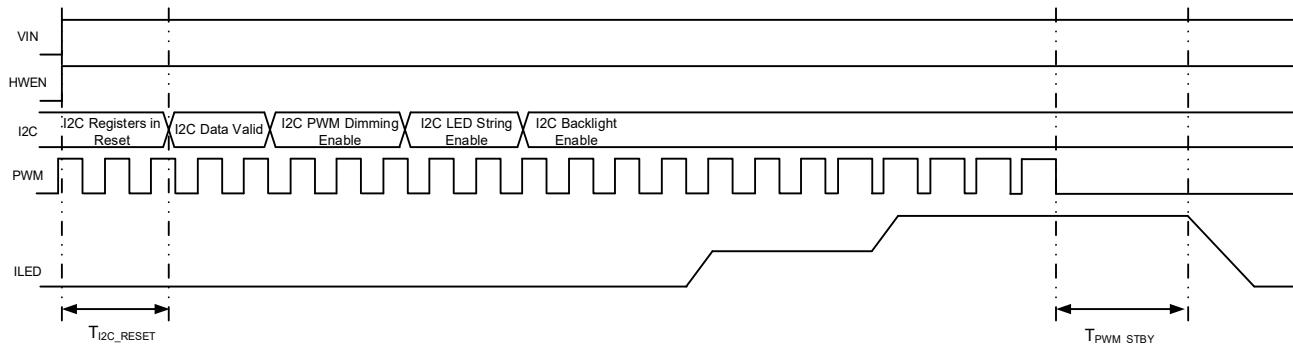


Figure 3. Enable of KTZ8869 via PWM

Operating Mode Description

The KTZ8869 backlight can operate in different modes, see Table 1 below.

Table 1. Backlight Operating Modes

HWEN	BL_EN 0x01[0]	PWM INPUT	I2C BRIGHTNESS 0x05[7:0] 0x04[3:0]	CURRENT SINKs ENABLEs 0x08[7:0]	PWM_EN 0x02[0]	FEEDBACK DISABLEs 0x10[7:0]	MAPPING MODE 0x02[3]	ACTION
0	X	X	X	X	X	X	X	Shutdown
1	0	X	X	X	X	X	X	Standby11
1	1	X	X	00000000	X	X	X	Standby11
1	1	X	0x000	X	X	X	X	Standby11
1	1	X	$\geq 0x001$	≥ 00000001	0	<11111111	0 = Gam. Mode 1 = Lin. Mode	-Backlight boost enabled -Selected current sink(s) enabled -I2C control only
1	1	Duty = 0	X	X	1	<11111111	X	Standby11
1	1	Duty > 0	$\geq 0x001$	≥ 000001	1	<11111111	0 = Gam. Mode 1 = Lin. Mode	-Backlight boost enabled -Selected current sink(s) enabled -I2C x PWM control
1	1	Duty > 0	$\geq 0x001$	≥ 00000001	1	11111111	0 = Gam. Mode 1 = Lin. Mode	-Backlight boost disabled -Selected current sink(s) enabled -I2C x PWM control

Backlight LED Current

The LED current is always a DC current (not PWM). It can be programmed for either Gamma 2.2 mapping mode or linear mapping mode by Register 0x02 bit [3]. These two modes determine the transfer characteristic of dimming code to LED current. It also has 12-bit control, including the 8-bit MSBs from register 0x05 bits [7:0] and the 4-bit LSBs from register 0x04 bits [3:0]. When programming 12-bit dimming ratio, the 4-bit LSBs should be programmed first, then the 8-bit MSBs are programmed. Only programming the 4-bit LSBs doesn't change the current ratio until the 8-bit MSBs are programmed.

In linear mapping 12-bit dimming mode, the LED current per channel can be calculated as:

$$I_{LED_BL} = I_{LED_FS} * D_{PWM} * \left(\frac{Code + 1}{4096} \right), \quad (Code = 1 \sim 4095)$$

where I_{LED_FS} is the backlight full-scale LED current which is programmed by register 0x15 bits [7:3] and register 0x11 bit [3], ranges from 5.2mA to 30mA with 0.8mA step or 5.74mA to 32.4mA with 0.86mA step, D_{PWM} is the input PWM duty cycle if PWM dimming is enabled, otherwise $D_{PWM} = 1$.

In Gamma 2.2 mapping 12-bit dimming mode, the LED current per channel is separated into two regions, they can be calculated as:

$$I_{LED_BL} = I_{LED_FS} * D_{PWM} * \left(\frac{Code + 216}{131162} \right) \quad (Code = 1 \sim 343)$$

$$I_{LED_BL} = I_{LED_FS} * D_{PWM} * \left(\frac{Code}{4095} \right)^{2.2} \quad (Code = 344 \sim 4095)$$

11. Standby signifies that the backlight boost and current sinks are shut down. Register writes are still possible. Shutdown signifies that the device was reset and no I2C communication is accepted.

For Code 0 of both linear and Gamma 2.2 mapping modes, current sink and boost converter will be disabled, LED will be turned off.

Backlight Brightness Control Mode

KTZ8869 has two brightness control mode, I²C Only Mode and I²C x PWM Mode, see Figure 4. In I²C Only Mode, register 0x02's bit [0] PWM_ENABLE should be set to "0", the LED brightness is controlled by registers 0x04 and 0x05. In I²C x PWM Mode, register 0x02's bit [0] PWM_ENABLE should be set to "1", the LED brightness will be controlled by I²C code and PWM duty together.

If the LED current is changed from one value to the other by I²C dimming Register 0x04 and Register 0x05, the ramp time can help LED current transit smoothly from one brightness level to next one. Ramp time can be adjusted up to 640ms via 0x03's bits [6:3]. Ramp time applies both to ramp up and ramp down, it remains same regardless the amount of change in brightness.

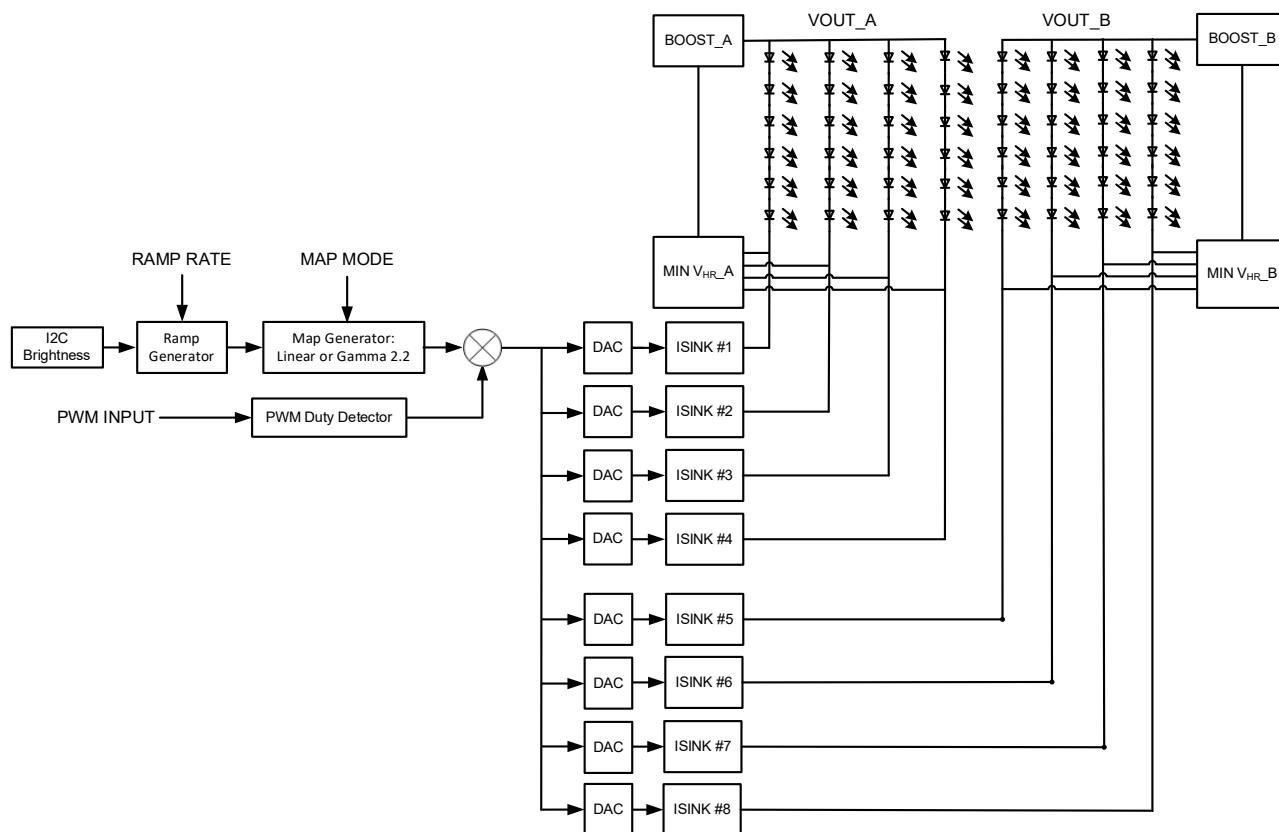


Figure 4. I²C and PWM Dimming Scheme

Backlight PWM Dimming

In backlight I²C x PWM Mode, the input PWM duty cycle is converted internally to produce a DC output sink current (not pulsing). When PWM is enabled, it can be programmed as either active high or active low by register 0x02's bit [2], with active high as default. When PWM dimming is enabled, KTZ8869 uses internal 20MHz sampling clock to detect the PWM duty cycle. It is recommended to have the minimum PWM on time as 0.1μs. For the example of 20kHz dimming frequency, the PWM duty cycle range can be 0.2%~100%. The PWM dimming frequency range can be as wide as 100Hz to 100kHz.

PWM Dimming Step Response and Timeout

If the LED current is changed from one value to the other by PWM dimming duty cycle, the transition ramp up/down time can be programmed by Register 0x15 bits [2:0]. For this transition ramp, its slope is fixed, so the final transition ramp time is dependent on the change amount of the PWM duty cycle.

The KTZ8869 PWM timeout feature turns off the boost output when the PWM is enabled and there is no PWM pulse detected.

PWM to Digital Code Readback

In I²C x PWM control mode, registers 0x12 and 0x13 contain the PWM duty cycle to the 11-bit code conversion information. Register 0x12 contains the 8 LSBs of the brightness code and register 0x13 the 3 MSBs. They are suggested to be read out in successive way to make sure the PWM duty result is correct. Too long delay between reading them may cause incorrect returned result, since input PWM duty may change during the delay time. To translate this reading to the actual LED current setting of the KTZ8869, convert it to the corresponding duty cycle and multiply it by the brightness level setting in the brightness registers (0x04 and 0x05).

Backlight PWM Hysteresis

In backlight mode, if PWM dimming frequency is high and PWM dimming duty cycle is low, even the internal fast 20MHz sampling clock's sampling error can be sufficient to cause the output LED current jitter. KTZ8869 implements PWM hysteresis control to minimize the jitter. It can be programmed by register 0x03 bits [2:0]. The input PWM duty cycle is converted to an internal 11-bit digital value, this PWM hysteresis decides how many LSBs of this 11-bit digital value is changed before the output LED current can follow the change. When PWM duty cycle changes in the same direction, no hysteresis exists. Only when the PWM duty cycle's change starts to go in different direction, does the hysteresis starts to take effect, and only when the change is larger or equal to the number of LSBs programmed, the output LED current starts to follow the change. Table 2 shows the relationship between the minimum LSB(s) and the PWM duty cycle hysteresis. Table 3 summarizes register 0x03 bits [2:0]'s minimum setting to prevent jitter under different input PWM frequency conditions. The drawback of setting PWM hysteresis too high is that the output current becomes less accurate due to the hysteresis.

Table 2. PWM Hysteresis

PWM Register 0x03 Bits [2:0]	Minimum LSB(s)	PWM Duty Cycle Hysteresis
000	0	0/2047 = 0%
001	2	2/2047 = 0.10%
010	4	4/2047 = 0.20%
011	6	6/2047 = 0.29%
100	8	8/2047 = 0.39%
101	10	10/2047 = 0.48%
110	12	12/2047 = 0.59%
111	14	14/2047 = 0.68%

Table 3. Register 0x03 Bits [2:0]’s Minimum Setting

PWM Dimming Frequency (kHz)	Sampling Error	Register 0x03 Bits [2:0]’s Minimum Setting to Prevent Jitter
0.1	0.0005%	001
1	0.005%	001
5	0.025%	001
10	0.05%	001
20	0.1%	010
40	0.2%	011
100	0.5%	110

Turn On/Off Ramp

When backlight mode is enabled from standby mode or disabled to standby mode, the LED current waveform’s turn on/off time is controlled by Turn On/Off Ramp Register 0x14 bits [7:4] and bits [3:0] respectively. The 16 options range from 512 μ s to 16384ms, with 8ms as default. The shape of the turn on/off ramp in backlight mode can also be programmed as exponential or linear through the Register 0x02 bit [1], with linear as default.

LED Fault Protection

Each current sink is protected against LED short or open conditions. The outcome of LED short event depends on the setting of LED_SHORT_MODE bit in register 0x11 bit [2]. If it is ‘1’ and LED short circuit condition arises, the current sink continues to regulate until $V_{SINK} > V_{SOV}$. When any sink node voltage goes above V_{SOV} (6V) for more than 59ms (typ.), LED_SHORT flag will be set in register 0x0F and that channel’s current sink will be turned off, and the other channel(s) will continue to work if they don’t trigger this fault condition. If it is ‘0’, the LED_SHORT flag will be set in register 0x0F when $V_{SINK} > V_{SOV}$ more than 59ms(typ.) is detected, but KTZ8869 will keep working as usual without turning off the shorted channel’s current sink until it reaches thermal shutdown.

In case of an LED failing open, the current sink voltage of the failed string will go close to ground and dominate the boost converter control loop. As a result, the output voltage will increase until it reaches the over-voltage threshold set by register 0x02 bit [7:5]. Once an OVP event has been detected, the boost will stop switching and the BL_OVP flag will be set in register 0x0F. The outcome of OVP event depends on the setting of OVP_MODE bit in register 0x02 bit [4]. If OVP_MODE is set to 0, the LED open channel will not be disabled, as soon as V_{BL_OUT} falls below the backlight OVP threshold, the KTZ8869 begins switching again, so that V_{BL_OUT} will be kept close to OVP threshold. Once the opened channel resumes to connected later, its LED current will resume and V_{BL_OUT} will go back to normal level. If OVP_MODE is set to 1, once the over-voltage incident is triggered, the BL_OVP flag is set in register 0x0F. Any of the enabled current sink headroom voltage drops below 150mV will be disabled. Then the output voltage of the boost converter will go back to normal level. During the entire process, the rest of the LED string (healthy LED string) would continue in normal operation. Even if the open channel is reconnected later, its LED current will not resume until toggling HWEN or sending software reset command or resetting backlight mode.

In case where all LED channels are open, once the output voltage of the boost converter reaches the over-voltage threshold, all the current sinks will be disabled internally, and the boost converter will stop switching. User needs to restart the IC by toggling HWEN or sending software reset command or resetting backlight mode.

Backlight Over Current Protection

The KTZ8869 has 4 different OCP thresholds (1.2A, 1.6A, 2.0A, and 2.5A) chosen by register 0x11 bits [1:0]. It is a cycle-by-cycle current limit by detecting low side power FET current. Once the threshold is triggered, the low side power FET will be turned off immediately for the rest of the switching cycle time. If enough overcurrent threshold events occur, the BL_OCP Flag (in register 0x0F) will be set.

Backlight Output Isolation Protection in Shutdown

The KTZ8869 provides an optional external P-MOSFET control at ENP/SD pin to isolate backlight's two boost converters' outputs from the input power supply when backlight mode is disabled. When I²C register 0x09 bit [0] is 0, ENP/SD pin works as SD function. When backlight is disabled, ENP/SD pin is floating, which can turn off external P-MOSFET through an external pullup resistor R1 typically 100kΩ shown in Figure 5. When backlight is enabled, ENP/SD pin will be pulled down through an internal 33kΩ resistor R2. The resistor ratio of R1 and R2 can be designed accordingly to turn on the external P-MOSFET. A capacitor C1 typically 100pF ~ 1nF can be used to limit the inrush current going through the P-MOSFET when it's turned on. A capacitor C2 typically 10μF can prevent big spikes at P-MOSFET's drain when the P-MOSFET is turned off while the currents through the two boost converters' inductors are not zero. Since the external P-MOSFET's Rdson affects the boost converter's efficiency, low Rdson P-MOSFET should be used. Considering the worst case of minimum VIN, its V_{TH} should also meet the following equation to make sure it can be fully turned on.

$$|V_{TH}| \ll VIN * \frac{R1}{R1 + R2}$$

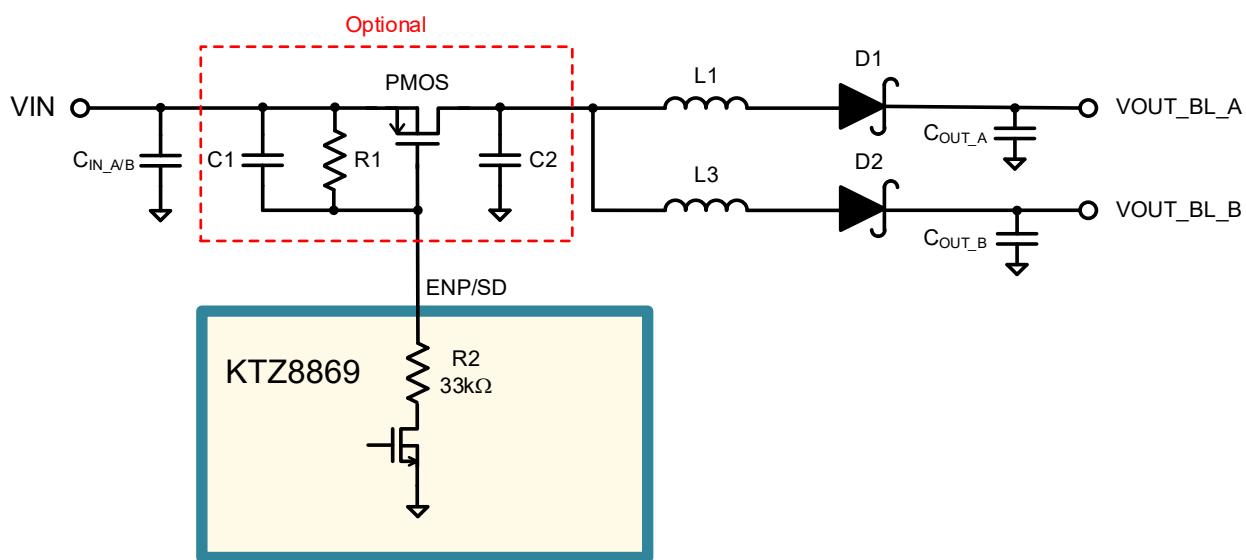


Figure 5. Optional External PMOS Control for Backlight Output Isolation

When I²C register 0x09 bit [0] is 1, ENP/SD pin works as ENP function.

LCD Bias Boost Converter

REG pin is the output of a high efficiency boost which is used to generate OUTP and OUTN power rails. REG boost ranges from 4V to 6.6V with 50mV step size. OUTP is generated by an LDO whose input is REG pin. OUTP ranges from 4V to 6.3V with 50mV step size and supports up to 300mA output current. OUTN is generated by an inverting charge pump whose input is REG pin. OUTN ranges from -6.3V to -4V with 50mV step size and supports up to 300mA output current. Refer to 0x0C, 0x0D, 0x0E for the settings of REG, OUTP and OUTN.

For proper operation, REG voltage is suggested to be $REG = MAX(OUTP, |OUTN|) + V_{HR_LCD}$, where $V_{HR_LCD} \geq 200mV$ for lower currents and $V_{HR_LCD} \geq 300mV$ for higher currents.

OUTP and OUTN voltage settings can be changed while they are enabled, but user must re-write register 0x09 to get new settings taking effect. The REG voltage changes immediately upon a register write. The LCD Bias

outputs can be turned on/off either by ENP and ENN pins or by 0x09 register bits [2:1]. EXT_EN bit in 0x09 is used to select on/off is controlled by external pins or internal register bits. Refer to Table 4 for detailed information.

Table 4. LCD Bias Power Operating Mode

HWEN	ENN	ENP	LCD_EN_MODE 0x09[7]	OUTP_EN 0x09[2]	OUTN_EN 0x09[1]	EXT_EN 0x09[0]	ACTION
0	X	X	X	X	X	X	Device shutdown
1	0	0	0	X	X	1	Standby ¹²
1	X	X	1	0	0	0	Standby ¹²
1	0	1	1	X	X	1	V_{OUTP} enabled via external input
1	1	0	1	X	X	1	V_{OUTN} enabled via external input
1	1	1	1	X	X	1	V_{OUTP} and V_{OUTN} enabled via external Input
1	X	X	1	1	0	0	V_{OUTP} enabled via I ² C
1	X	X	1	0	1	0	V_{OUTN} enabled via I ² C
1	X	X	1	1	1	0	V_{OUTP} and V_{OUTN} enabled via I ² C

Fast Discharge

KTZ8869 has internal switch resistance for discharging OUTP and OUTN when device is shutdown. The OUTP discharge function is enabled with register 0x09 bit [4] and the OUTN discharge is enabled with register 0x09 bit [3].

OUTP Short Circuit Protection

If output current of OUTP is greater than 380mA (typical), the OUTP_SHORT flag will be set in register 0x0F. A I²C readback is required to clear the flag. The outcome of an OUTP_SHORT detection depends on the setting of register 0x0A bits [7:6], including report-only flag, shutdown OUTP/OUTN, and shutdown OUTP/OUTN and backlight. KTZ8869 provides four level short circuit detection filter: 100μs, 500μs, 1ms, and 2ms by register 0x0B bits [3:2] to avoid false trigger problems.

OUTN Short Circuit Protection

OUTN_SHORT flag will be set in register 0x0F if OUTN is found shorted to ground. An I²C readback of register 0x0F is required to clear the flag. The outcome of an OUTN_SHORT detection depends on the setting of register 0x0A bits [7:6], including report-only flag, shutdown OUTP/OUTN, and shutdown OUTP/OUTN and backlight. KTZ8869 provides four level short circuit detection filter options: 100μs, 500μs, 1ms, and 2ms by register 0x0B bits [1:0] to avoid false trigger problems.

Soft Reset

All the I²C registers can be reset to their default settings by writing '1' to the SOFTWARE_RESET bit in Register 0x01, this bit will be reset to '0' automatically after the software reset.

UVLO

Under voltage lock-out (UVLO) featured is included to monitor the input voltage VIN. Once VIN drops below UVLO falling threshold, the current sinks are disabled, and the boost converters stop switching. After VIN increases above UVLO rising threshold, the boost converters and the current sinks will resume to their previous setting.

12. Standby signifies that OUTP and OUTN are either high impedance or being internally pulled low via the active pulldown, and that the LCD boost is off. Shutdown signifies that the device was reset and no I²C communication is accepted.

Thermal Shutdown

The KTZ8869 has Thermal Shutdown Protection which will turn off the backlight boost, all current sinks, LCD bias boost, inverting charge pump, and the LDO when the die temperature reaches or exceeds 150°C (typ). The I²C access is still available during Thermal Shutdown event, but TSD flag will be set in register 0x0F, this bit is real time reflection of TSD. When TSD is gone, the bit will be reset back to 0 automatically.

Device Functional Modes

Shutdown: The KTZ8869 is in shutdown when the HWEN pin is low. I²C writes are not recognized in shutdown.

Standby: After the HWEN pin is set high the KTZ8869 goes into standby mode. In standby mode, I²C writes are allowed but references, bias currents, the oscillator, LCD Bias, and backlight are all disabled to keep the quiescent supply current low.

Normal mode: Each of the main blocks of the KTZ8869 are independently controlled. For details on how to control each mode, see Tables 1 and 4.

Application Information

I²C Serial Data Bus

KTZ8869 supports the I²C bus protocol. A device that sends data onto the bus is defined as a transmitter and a device receiving data as a receiver. The device that controls the bus is called a master, whereas the devices controlled by the master are known as slaves. A master device must generate the serial clock (SCL), control bus access and generate START and STOP conditions to control the bus. KTZ8869 operates as a slave on the I²C bus. Within the bus specifications a standard mode (100kHz maximum clock rate) and a fast mode (400kHz maximum clock rate) are defined. KTZ8869 works in both modes. Connections to the bus are made through the open-drain I/O lines SDA and SCL.

The following bus protocol has been defined in Figure :

- Data transfer may be initiated only when the bus is not busy.
- During data transfer, the data line must remain stable whenever the clock line is HIGH. Changes in the data line while the clock line is high are interpreted as control signals.

Accordingly, the following bus conditions have been defined:

Bus Not Busy

Both data and clock lines remain HIGH.

Start Data Transfer

A change in the state of the data line, from HIGH to LOW, while the clock is HIGH, defines a START condition.

Stop Data Transfer

A change in the state of the data line, from LOW to HIGH, while the clock line is HIGH, defines the STOP condition.

Data Valid

The state of the data line represents valid data when, after a START condition, the data line is stable for the duration of the HIGH period of the clock signal. The data on the line must be changed during the LOW period of the clock signal. There is one clock pulse per bit of data.

Each data transfer is initiated with a START condition and terminated with a STOP condition. The number of data bytes transferred between START and STOP conditions are not limited and are determined by the master device. The information is transferred byte-wise and each receiver acknowledges with a ninth bit.

Acknowledge

Each receiving device, when addressed, is obliged to generate an acknowledge after the reception of each byte. The master device must generate an extra clock pulse that is associated with this acknowledge bit.

A device that acknowledges must pull down the SDA line during the acknowledge clock pulse in such a way that the SDA line is stable LOW during the HIGH period of the acknowledge-related clock pulse. Setup and hold times must also be taken into account.

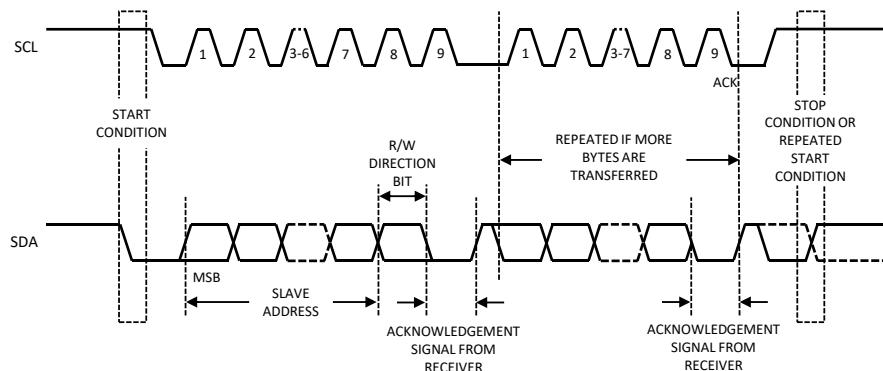


Figure 6. Data Transfer on I²C Serial Bus

KTZ8869 7-bit slave device address is 0010001 binary (0x11h).

There are two kinds of I²C data transfer cycles: write cycle and read cycle.

I²C Write Cycle

For I²C write cycle, data is transferred from a master to a slave. The first byte transmitted is the 7-bit slave address plus one bit of '0' for write. Next follows a number of data bytes. The slave returns an acknowledge bit after each received byte. Data is transferred with the most significant bit (MSB) first. Figure shows the sequence of the I²C write cycle.

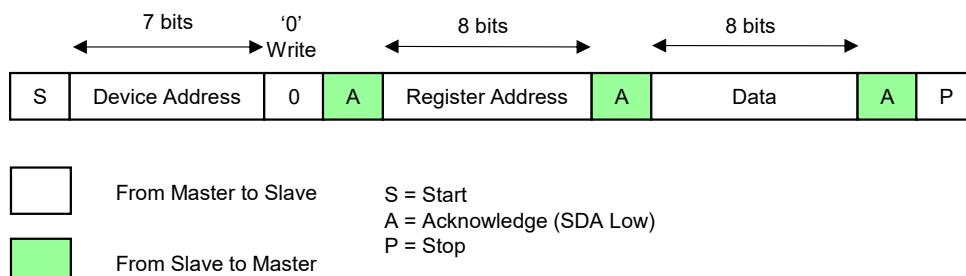


Figure 7. I²C Write Cycle

I²C Write Cycle Steps:

- Master generates start condition.
- Master sends 7-bit slave address (0010001 for KTZ8869) and 1-bit data direction '0' for write.
- Slave sends acknowledge if the slave address is matched.
- Master sends 8-bit register address.
- Slave sends acknowledge.
- Master sends 8-bit data for that addressed register.
- Slave sends acknowledge.
- If master sends more data bytes, the register address will be incremented by one after each acknowledge.
- Master generates stop condition to finish the write cycle.

I²C Read Cycle

For I²C read cycle, data is transferred from a slave to a master. But to start the read cycle, master needs to write the register address first to define which register data to read. Figure shows the steps of the I²C read cycle.

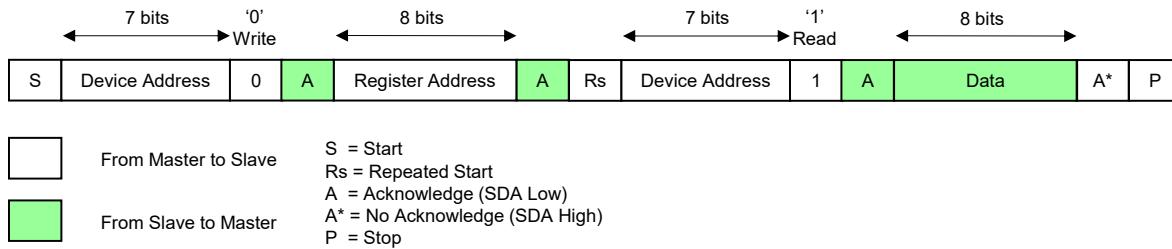


Figure 8. I²C Read Cycle

I²C Read Cycle Steps:

- Master generates start condition.
- Master sends 7-bit slave address (0010001 for KTZ8869) and 1-bit data direction '0' for write.
- Slave sends acknowledge if the slave address is matched.
- Master sends 8-bit register address.
- Slave sends acknowledge.
- Master generates repeated start condition.
- Master sends 7-bit slave address (0010001 for KTZ8869) and 1-bit data direction '1' for read.
- Slave sends acknowledge if the slave address is matched.
- Slave sends the data byte of that addressed register.
- If master sends acknowledge, the register address will be incremented by one after each acknowledge and the slave will continue to send the data for the updated addressed register.
- If master sends no acknowledge, the slave will stop sending the data.
- Master generates stop condition to finish the read cycle.

I²C Register Map

Table 5 summarizes KTZ8869's 20 I²C registers, their read/write settings and default values. They can be reset to default values by VIN power on reset, toggling HWEN or I²C software reset.

Table 5. I²C Register Map

Register Name	Address (Hex)	R/W	Default Value
Device ID	0x00	R	0x2B
BACKLIGHT ENABLE	0x01	R/W	0x00
BL_CFG1	0x02	R/W	0xFA
BL_CFG2	0x03	R/W	0x8D
BL_BRT_LSB	0x04	R/W	0x0F
BL_BRT_MSB	0x05	R/W	0xFF
BL_EN	0x08	R/W	0xFF
LCD_BIAS_CFG1	0x09	R/W	0x18
LCD_BIAS_CFG2	0x0A	R/W	0x11
LCD_BIAS_CFG3	0x0B	R/W	0x00
LCD_BOOST_CFG	0x0C	R/W	0x28
OUTP_CFG	0x0D	R/W	0x1E
OUTN_CFG	0x0E	R/W	0x1C
FLAG	0x0F	R	0x00
BL_OPTION1	0x10	R/W	0x00
BL_OPTION2	0x11	R/W	0x77
PWM2DIG_LSBs	0x12	R	0x00
PWM2DIG_MSBs	0x13	R	0x00
TURN_ON/OFF_RAMP	0x14	R/W	0x44
PWM_UP/DOWN_RAMP and IFS	0x15	R/W	0xF8

Table 6. Device ID Register

ADDRESS	MODE		RESET VALUE: 0x2B
0x00	R		
BIT	NAME	POR	DESCRIPTION
7:6	RSVD	00	Reserved
5:3	Device ID	101	Device ID
2:0	Revision	011	Revision

Table 7. BACKLIGHT ENABLE REGISTER

ADDRESS	MODE		RESET VALUE: 0x00
0x01	R/W		
BIT	NAME	POR	DESCRIPTION
7	Software RESET	0	0: Disable (Default) 1: Reset (automatically returns to 0)
6	RSVD	0	Reserved, default as: 0
5	RSVD	0	Reserved, default as: 0
4	RSVD	0	Reserved, default as: 0
3	RSVD	0	Reserved, default as: 0
2	RSVD	0	Reserved, default as: 0
1	RSVD	0	Reserved, default as: 0
0	Backlight Enable	0	0: Disable (Default) 1: Enable (Can be reset by VPOS / VNEG short)

Note: Writing software reset bit to '1' will reset all I²C registers to their default values, then this bit will be internally reset back to '0'.

Table 8. BL_CFG1 Register

ADDRESS	MODE		RESET VALUE: 0xFA
0x02	R/W		
BIT	NAME	POR	DESCRIPTION
7:5	BL_OVP	111	Backlight OVP 000: 21.4V 001: 26.4V 010: 31.5V 011: 36.5V 100: 23.9V 101: 29.0V 110: 34.0V 111: 40.0V (Default)
4	OVP_MODE	1	0: OVP is report only 1: OVP will turn off the fault string that causes OVP event. (Default)
3	BLED_MAP	1	0: Gamma 2.2 1: Linear (Default)
2	PWM_CONFIG	0	0: Active high (Default) 1: Active low
1	RAMP_SHAPE	1	0: Exponential 1: Linear (Default)
0	PWM_ENABLE	0	0: PWM disabled (Default) 1: PWM enabled

Note: When Backlight Current Mapping setting is changed, the LED current change will not take effect until Register 0x05 is programmed.

Table 9. BL_CFG2 Register

ADDRESS	MODE		RESET VALUE: 0x8D
0x03	R/W		
BIT	NAME	POR	DESCRIPTION
7	RSVD	1	Reserved (Must be 1)
6:3	LED CURRENT RAMP	0001	<p>Controls backlight LED current ramping time.</p> <p>0000: 1µs/step 0001: 2µs/step (Default) 0010: 4µs/step 0011: 8µs/step 0100: 16µs/step 0101: 32µs/step 0110: 64ms (fixed) 0111: 128ms (fixed) 1000: 192ms (fixed) 1001: 256ms (fixed) 1010: 320ms (fixed) 1011: 384ms (fixed) 1100: 448ms (fixed) 1101: 512ms (fixed) 1110: 576ms (fixed) 1111: 640ms (fixed)</p>
2:0	PWM_HYST	101	<p>Sets the minimum change in PWM input duty cycle that results in a change of backlight LED brightness level.</p> <p>000: 0 LSB 001: 2 LSBs 010: 4 LSBs 011: 6 LSBs 100: 8 LSBs 101: 10 LSBs (Default) 110: 12 LSBs 111: 14 LSBs</p>

1. About LED CURRENT RAMP Time in the table, for "0000" ~ "0101" settings, the ramp slope is fixed, the final ramp time is proportional to the 12-bit current steps from the one level to the other. For "0110" ~ "1111" settings, the ramp times are fixed when current ramps from one level to the other.

Table 10. BL_BRT_LSB Register

ADDRESS	MODE		RESET VALUE: 0x0F
0x04	R/W		
BIT	NAME	POR	DESCRIPTION
7:4	RSVD	0000	
3:0	BRT [3:0]	1111	4-bit brightness code LSBs

Table 11. BL_BRT_MSB Register

ADDRESS	MODE		RESET VALUE: 0xFF
0x05	R/W		
BIT	NAME	POR	DESCRIPTION
7:0	BRT [7:0]	11111111	8-bit brightness code MSBs

Note:

1. When programming 12-bit current ratio, the 4-bit LSBs should be programmed first, then the 8-bit MSBs can be programmed to take effect. Even if only the 4-bit LSBs need to be changed, the 8-bit MSB should always be programmed to make the 4-bit LSBs change taking effect.
2. For 12-bit program code 12'b000000000000, both boost converter and current sinks are turned off.

Table 12. BL_EN Register

ADDRESS	MODE		RESET VALUE: 0xFF
0x08	R/W		
BIT	NAME	POR	DESCRIPTION
7	LED8_EN	1	0 = Current sink 8 disabled 1 = Current sink 8 enabled (Default)
6	LED7_EN	1	0 = Current sink 7 disabled 1 = Current sink 7 enabled (Default)
5	LED6_EN	1	0 = Current sink 6 disabled 1 = Current sink 6 enabled (Default)
4	LED5_EN	1	0 = Current sink 5 disabled 1 = Current sink 5 enabled (Default)
3	LED4_EN	1	0 = Current sink 4 disabled 1 = Current sink 4 enabled (Default)
2	LED3_EN	1	0 = Current sink 3 disabled 1 = Current sink 3 enabled (Default)
1	LED2_EN	1	0 = Current sink 2 disabled 1 = Current sink 2 enabled (Default)
0	LED1_EN	1	0 = Current sink 1 disabled 1 = Current sink 1 enabled (Default)

Table 13. LCD_CFG1 Register

ADDRESS	MODE		RESET VALUE: 0x18
0x09	R/W		
BIT	NAME	POR	DESCRIPTION
7	LCD_EN	0	0 = Bias supply off (I²C and external) (Default) 1 = Normal mode
6	CP_FREQ_MIN	0	Negative charge pump minimum switching frequency 0 = 8kHz (Default) 1 = 32kHz
5	RSVD	0	
4	OUTP_DISCH	1	0 = No pulldown on OUTP 1 = Pulldown on OUTP when in shutdown (Default)
3	OUTN_DISCH	1	0 = No pulldown on OUTN 1 = Pulldown on OUTN when in shutdown (Default)
2	OUTP_EN	0	0 = OUTP disabled (Default) 1 = OUTP enabled
1	OUTN_EN	0	0 = OUTN disabled (Default) 1 = OUTN enabled
0	EXT_EN	0	Activates external enables (ENP and ENN) 0 = External enables are disabled. OUTP and OUTN can only be enabled via bit OUTP_EN and OUTN_EN, respectively. ENP/SD pin works as SD function to control optional external PMOS to disconnect the two backlight boost converters' outputs from the input when backlight mode is disabled. (Default) 1 = External enables are enabled. OUTP and OUTN can only be enabled via pin ENP and ENN, respectively. ENP/SD pin works as ENP function to enable OUTP.

Table 14. LCD_CFG2 Register

ADDRESS	MODE		RESET VALUE: 0x11
0x0A	R/W		
BIT	NAME	POR	DESCRIPTION
7:6	BIAS_SHORT_MODE	00	0X = Flag only (Default) 10 = Flag + shutdown V_{OUTP}/V_{OUTN} 11 = Flag + shutdown V_{OUTP}/V_{OUTN} /Backlight
5:4	VOUTP_RAMP	01	V_{OUTP} ramp time, low to high: 00 = 228 μ s 01 = 456μs (Default) 10 = 684 μ s 11 = 912 μ s
3:0	VOUTN_RAMP	0001	V_{OUTN} ramp time, high to low: 0000 = 456 μ s 0001 = 912μs (Default) 0010 = 1368 μ s 0011 = 1824 μ s 0100 = 2280 μ s 0101 = 2736 μ s 0110 = 3192 μ s 0111 = 3648 μ s 1000 = 4104 μ s 1001 = 4560 μ s 1010 = 5016 μ s 1011 = 5472 μ s 1100 = 5928 μ s 1101 = 6384 μ s 1110 = 6840 μ s 1111 = 7296 μ s

Note:

1. For VOUTP_RAMP time, it is fixed slew rate ramp strategy, the ramp time value is given by assuming OUTP = 5.75V. If OUTP is set 5.5V and VOUTP_RAMP = 01, then actual ramp time will be 456*5.5/5.75 = 436 μ s.
2. For VOUTN_RAMP time, it is fixed slew rate ramp strategy, the ramp time value is given by assuming OUTN = -5.75V. If OUTN is set -5.5V and VOUTN_RAMP = 0001, then actual ramp time will be 912*5.5/5.75 = 872 μ s.

Table 15. LCD_CFG3 Register

ADDRESS	MODE		RESET VALUE: 0x00
0x0B	R/W		
BIT	NAME	POR	DESCRIPTION
7:4	RSVD	0000	
3:2	VOUTP_SC_FILT	00	OUTP short circuit filter timer 00 = 2ms (Default) 01 = 1ms 10 = 500 μ s 11 = 100 μ s
1:0	VOUTN_SC_FILT	00	OUTN short circuit filter timer 00 = 2ms (Default) 01 = 1ms 10 = 500 μ s 11 = 100 μ s

Table 16. LCD_BOOST_CFG Register

ADDRESS	MODE		RESET VALUE: 0x28
0x0C	R/W		
BIT	NAME	POR	DESCRIPTION
7:6	RSVD	00	
5:0	REG	101000	REG voltage (50-mV steps): REG = 4V + (Code × 50mV) 000000 : 4V 000001 : 4.05V : 101000 : 6V (Default) : >=110100 : 6.6V

Table 17. OUTP_CFG Register

ADDRESS	MODE		RESET VALUE: 0x1E
0x0D	R/W		
BIT	NAME	POR	DESCRIPTION
7:6	RSVD	00	
5:0	OUTP	011110	OUTP voltage (50mV steps): V _{OUTP} = 4V + (Code × 50mV), 6.3V max 000000 : 4V 000001 : 4.05V : 011110 : 5.5V (Default) : >=101110 : 6.3V

Note: Writing to Register 0x0D will not take effect immediately, until Register 0x09 is written again.

Table 18. OUTN_CFG Register

ADDRESS	MODE		RESET VALUE: 0x1C
0x0E	R/W		
BIT	NAME	POR	DESCRIPTION
7:6	RSVD	00	
5:0	OUTN	011100	OUTN voltage (-50mV steps): V _{OUTN} = -4 V - (Code × 50mV), -6.3V min 000000 : -4 V 000001 : -4.05V : 011100 : -5.4V (Default) : >=101110 : -6.3V

Note: Writing to Register 0x0E will not take effect immediately, until Register 0x09 is written again.

Table 19. FLAG Register

ADDRESS	MODE		RESET VALUE: 0x00
0x0F	R		
BIT	NAME	POR	DESCRIPTION
7	LED_SHORT	0	0 = Normal operation 1 = LED short protection triggered
6	TSD	0	0 = Normal operation 1 = Thermal shutdown triggered (die temperature > 150°C)
5	OUTP_SHORT	0	0 = Normal operation 1 = OUTP output has hit the overcurrent threshold
4	OUTN_SHORT	0	0 = Normal operation 1 = OUTN > 0.9 × V_{OUTN_target}
3	BL_GROUPB_OVP	0	0 = Normal operation 1 = Backlight boost outputB > OVP threshold
2	BL_GROUPA_OVP	0	0 = Normal operation 1 = Backlight boost outputA > OVP threshold
1	BL_GROUPB_OCP	0	0 = Normal operation 1 = Backlight boost outputB switch current > OCP threshold
0	BL_GROUPA_OCP	0	0 = Normal operation 1 = Backlight boost outputA switch current > OCP threshold

Note:

1. TSD is real-time results.
2. LED_SHORT, OUTP_SHORT, OUTN_SHORT, BL_OVP and BL_OCP are latched results; OUTP_SHORT, OUTN_SHORT, BL_OVP and BL_OCP can be reset by reading back 0x0F.
3. All the status bits can be reset by VIN power on reset, software reset or toggling HWEN.

Table 20. BL_OPTION1 Register

ADDRESS	MODE		RESET VALUE: 0x00
0x10	R/W		
BIT	NAME	POR	DESCRIPTION
7	LED8_FB_DISABLE	0	0 = Feedback enabled (Default) 1 = Feedback disabled
6	LED7_FB_DISABLE	0	0 = Feedback enabled (Default) 1 = Feedback disabled
5	LED6_FB_DISABLE	0	0 = Feedback enabled (Default) 1 = Feedback disabled
4	LED5_FB_DISABLE	0	0 = Feedback enabled (Default) 1 = Feedback disabled
3	LED4_FB_DISABLE	0	0 = Feedback enabled (Default) 1 = Feedback disabled
2	LED3_FB_DISABLE	0	0 = Feedback enabled (Default) 1 = Feedback disabled
1	LED2_FB_DISABLE	0	0 = Feedback enabled (Default) 1 = Feedback disabled
0	LED1_FB_DISABLE	0	0 = Feedback enabled (Default) 1 = Feedback disabled

Note: If all LED1~LED4 feedback disabled, Boost_A stops switching. If all LED5~LED8 feedback disabled, Boost_B stops switching.

Table 21. BL_OPTION2 Register

ADDRESS	MODE		RESET VALUE: 0x77
0x11	R/W		
BIT	NAME	POR	DESCRIPTION
7:6	BL_L_SELECT	01	00 = 6.8 μ H 01 = 4.7μH (Default) 10 = 10 μ H 11 = 10 μ H
5:4	RSVD	11	
3	BL_IFS_MAX	0	Backlight maximum full-scale current 0 = 30mA (Default) 1 = 32.4mA
2	LED_SHORT_MODE	1	0 = Keep fault string on 1 = Turn off fault string (Default)
1:0	BL_CURRENT_LIMIT	11	00 = 1.2A 01 = 1.6A 10 = 2.0A 11 = 2.5A (Default)

Table 22. PWM2DIG_LSBs Register

ADDRESS	MODE		RESET VALUE: 0x00
0x12	R		
BIT	NAME	POR	DESCRIPTION
7:0	PWM_TO_DIG	00000000	11-bit PWM-to-digital conversion code LSBs

Table 23. PWM2DIG_MSBs Register

ADDRESS	MODE		RESET VALUE: 0x00
0x13	R		
BIT	NAME	POR	DESCRIPTION
7:3	RSVD	00000	
2:0	PWM_TO_DIG	000	11-bit PWM-to-digital conversion code MSBs

Note: 0x12 and 0x13 are suggested to be read out in successive way to make sure the PWM duty result is correct. Too long delay between reading them may cause incorrect returned result, since input PWM may change during the delay time.

Table 24. TURN_ON/OFF_RAMP Register

ADDRESS	MODE		RESET VALUE: 0x44
0x14	R/W		
BIT	NAME	POR	DESCRIPTION
7:4	RAMP_ON_TIME	0100	On Ramp Time 0000 : 512µs 0001 : 1ms 0010 : 2ms 0011 : 4ms 0100 : 8ms (Default) 0101 : 16ms 0110 : 32ms 0111 : 64ms 1000 : 128ms 1001 : 256ms 1010 : 512ms 1011 : 1024ms 1100 : 2048ms 1101 : 4096ms 1110 : 8192ms 1111 : 16384ms
3:0	RAMP_OFF_TIME	0100	Off Ramp Time 0000 : 512µs 0001 : 1ms 0010 : 2ms 0011 : 4ms 0100 : 8ms (Default) 0101 : 16ms 0110 : 32ms 0111 : 64ms 1000 : 128ms 1001 : 256ms 1010 : 512ms 1011 : 1024ms 1100 : 2048ms 1101 : 4096ms 1110 : 8192ms 1111 : 16384ms

Table 25. PWM_UP/DOWN_RAMP Register

ADDRESS	MODE		RESET VALUE: 0xF8
0x15	R/W		
BIT	NAME	POR	DESCRIPTION
7:3	IFS	11111	<p>Backlight Full-scale LED Current ILED_FS</p> <p>If Reg0x11[3]=0, ILED_FS = 5.2+Code*0.8mA 11111 : 30mA (Default) 00001 : 6.0mA 00000 : 5.2mA</p> <p>If Reg0x11[3]=1, ILED_FS = 5.74+Code*0.86mA 11111 : 32.4mA (Default) 00001 : 6.6mA 00000 : 5.74mA</p>
2:0	PWM_RAMP_TIME	000	<p>PWM Duty Cycle Transition Ramp Time</p> <p>000 : 2ms (Default) 001 : 4ms 010 : 8ms 011 : 16ms 100 : 32ms 101 : 64ms 110 : 128ms 111 : 256ms</p>

Note: The PWM Dimming Transition Ramp Time in the table is defined as the time to change between minimum PWM duty cycle and the maximum PWM duty cycle. The final transition time is the multiplication of the time in the table and the change of the PWM duty cycle.

Capacitor Selection for Backlight Driver

Small size ceramic capacitors with low ESR are ideal for all applications. A 10 μ F input capacitor and a 1 μ F output capacitor are suggested. The voltage rating of these capacitors should exceed the maximum possible voltage at the corresponding pins, and these capacitors should be as close as possible to the IC. Table 25 shows the recommended capacitor vendors.

Table 26. Recommended Capacitor Vendors

Manufacturer	Website
Murata	www.murata.com
AVX	www.avx.com
Taiyo Yuden	www.t-yuden.com

Inductor Selection for Backlight Driver

An inductor of 4.7 μ H to 10 μ H with low DCR can be selected for the boost converter. To decide the current rating of the inductor required for the application, the following equation can be used to estimate the peak inductor current I_{PEAK} in continuous conduction mode (CCM):

$$I_{PEAK} = \frac{V_{OUT(MAX)} \times I_{OUT(MAX)}}{V_{IN(MIN)} \times \eta} + \frac{V_{IN(MIN)}}{2L \times F_{SW}} \times \left(1 - \frac{V_{IN(MIN)}}{V_{OUT(MAX)}}\right)$$

where $V_{OUT(MAX)}$ is the maximum output voltage, $V_{IN(MIN)}$ is the minimum input voltage, $I_{OUT(MAX)}$ is the maximum output current, F_{SW} is the boost converter's switching frequency, L is the inductor value, η is the boost converter's efficiency under that condition. **Table 27** shows recommended inductors under different application conditions.

Table 27. Recommended Inductors

Value (μ H)	Manufacturer	Inductor Part Number	DCR (Ω)	Saturation Current (A)	EIA Size (mm)
4.7	TDK	VLS3012HBX-4R7M	0.175	2.51	3.0×3.0×1.2
4.7	TAIYO YUDEN	NRS6028T 4R7MMGK	0.031	2.7	6.0×6.0×2.8

Schottky Diode Selection

Using a schottky diode is recommended because of its low forward voltage drop and fast reverse recovery time. The average current rating of the schottky diode should exceed the maximum output current, and its peak current rating should exceed the peak inductor current. Its voltage rating should also exceed the OVP setting. **Table 28** shows the recommended schottky diode.

Table 28. Recommended Schottky Diode

Application	Schottky Diode Part Number	Forward Voltage (V)	Forward Current (A)	Reverse Voltage (V)	Manufacturer
All	PMEG6010CEGWX	0.57	1	60	Nexperia

Capacitor Selection for Dual Output Bias

Small size ceramic capacitors with low ESR are ideal for all applications. A 10µF output capacitor at REG, OUTP and OUTN are suggested. Higher capacitor values can be used to improve the load transient response. The voltage rating of these capacitors should exceed the maximum possible voltage at the corresponding pins, and these capacitors should be as close as possible to the IC.

Flying Capacitor Selection for Bias

The charge pump needs an external flying capacitor. The minimum value for smartphone application is 4.7µF and 10µF for tablet application. Special care must be taken while choosing the flying capacitor as it will directly impact the output voltage accuracy and load regulation performance.

Inductor Selection for Dual Output Bias

An inductor in the range of 2.2µH to 10µH with low DCR can be selected for the boost converter. To estimate the inductance required for applications, calculate the maximum input average current as the following

$$I_{IN(MAX)} = \frac{V_{OUT} \cdot I_{OUT(MAX)}}{V_{IN} \cdot \eta}$$

Where, η is the converter efficiency and can be approximated as 90% for the typical case. In order to have smaller current ripple (to improve efficiency and minimize output voltage ripple), larger inductance will be required. If inductor ripple current needs to be less than 40% of the average input current, then

$$\Delta I_L = \frac{V_{IN} \cdot D \cdot T_S}{L} \leq 40\% \cdot \frac{V_{OUT} \cdot I_{OUT(MAX)}}{V_{IN} \cdot \eta}$$

Where duty cycle can be estimated as

$$D = \frac{V_{OUT} - V_{IN}}{V_{OUT}}$$

Then

$$\Delta I_L = \frac{V_{IN} \cdot (V_{OUT} - V_{IN}) \cdot T_S}{L \cdot V_{OUT}} \leq 40\% \cdot \frac{V_{OUT} \cdot I_{OUT(MAX)}}{V_{IN} \cdot \eta}$$

Therefore, the inductance can be calculated as

$$L \geq \frac{V_{IN}^2 \cdot (V_{OUT} - V_{IN}) \cdot \eta}{40\% \cdot V_{OUT}^2 \cdot I_{OUT(MAX)} \cdot f_S}$$

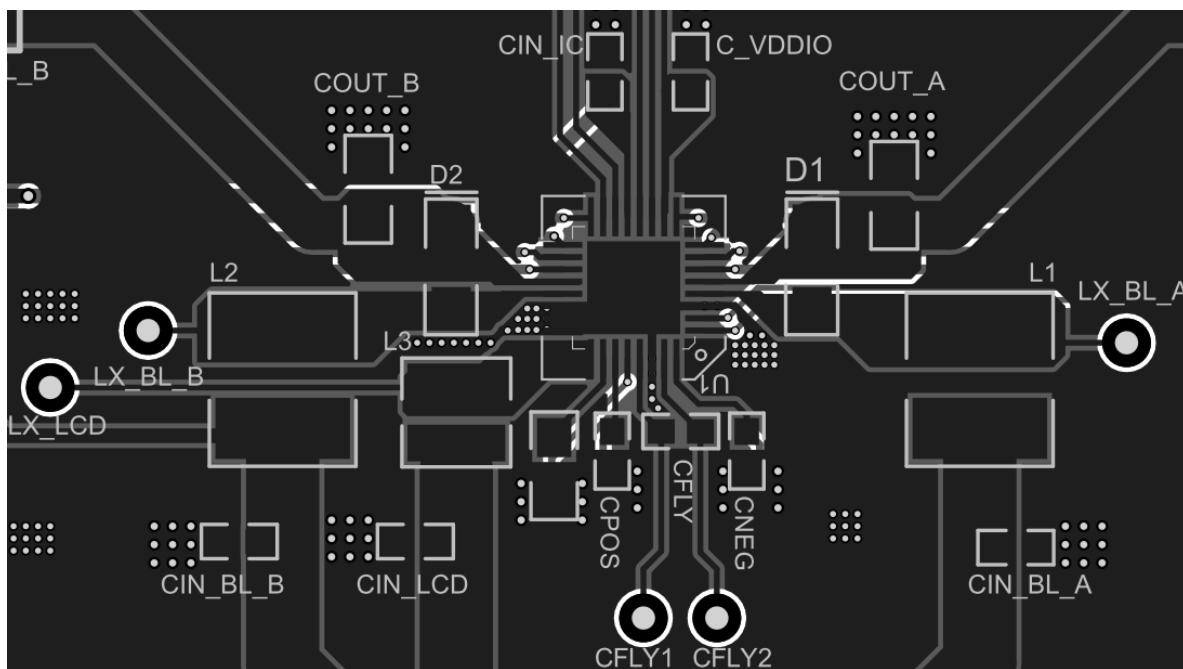
Where, f_S is the switching frequency of the boost converter.

Table 28. Recommended Inductor Part Numbers

Value (μ H)	Manufacturer	Inductor Part Number	DCR (Ω)	Saturation Current (A)	EIA Size (mm)
2.2	Toko	DFE201612P-2R2M	0.12	2.1	2 x 1.6 x 1.0
2.2	CYCTEC	HMLQ25201T-2R2MSR	0.102	3	2.5 x 2.0 x 1.0

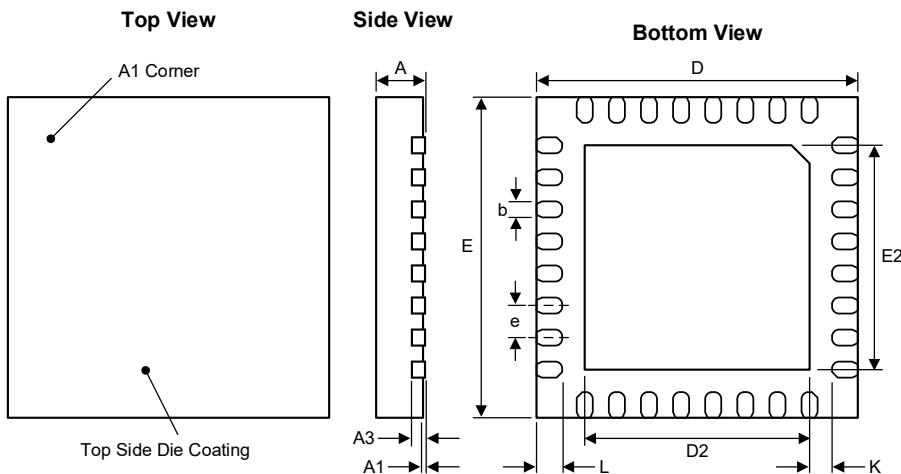
Recommended PCB Layout

PCB layout is very important for high frequency switching regulators in order to keep the loop stable and minimize noise. The input capacitor (C_{IN}) should be very close to the IC's VIN pin and PGND pin in order to get the best decoupling. The path between the inductor, LX pin, schottky diode and the output capacitor (C_{OUT}) should be kept as short as possible to minimize noise and ringing. To reduce power loss, the trace through the inductor, LX pin, schottky diode and C_{OUT} should be as short and wide as possible. Both input and output capacitors' GND terminals should be connected together on the PCB top layer and on the bottom layer GND plane.


Figure 9. Recommended PCB Layout

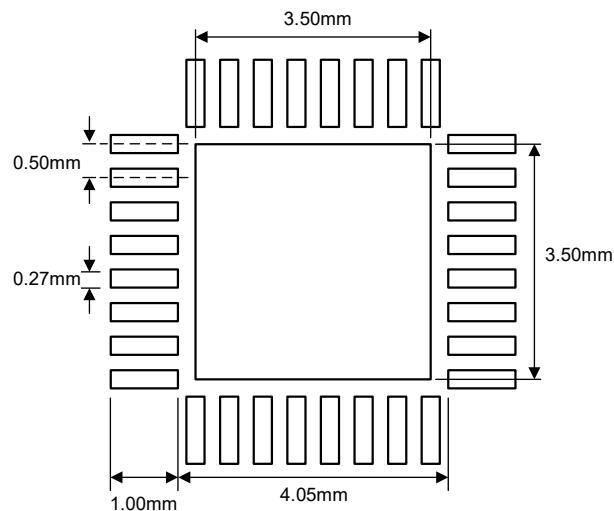
Packaging Information

WQFN55-32 (5.00mm x 5.00mm x 0.75mm)



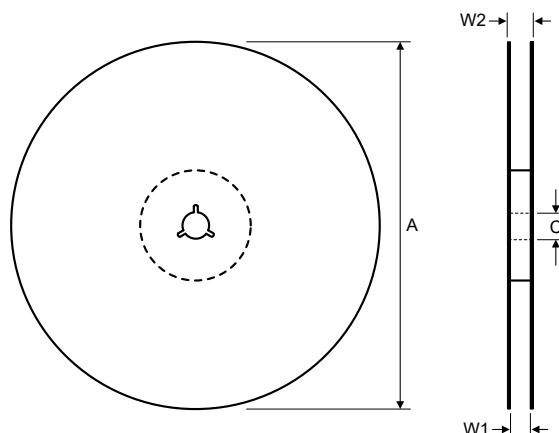
Dimension	mm		
	Min.	Typ.	Max.
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A3	0.203 REF		
b	0.20	0.25	0.30
D	—	5.00	—
D2	3.40	3.50	3.60
E	—	5.00	—
E2	3.40	3.50	3.60
e	0.50 BSC		
K	—	0.35	—
L	0.30	0.40	0.50

Recommended Footprint

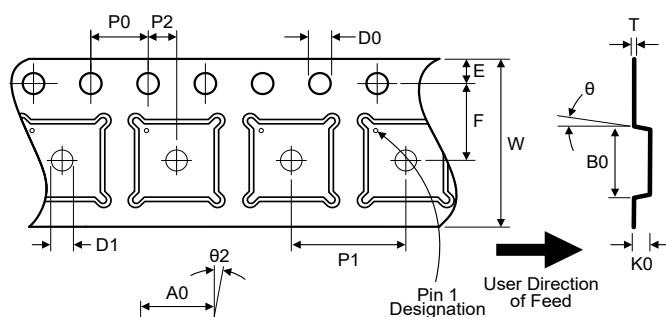


Packing Material Information

Reel Dimensions



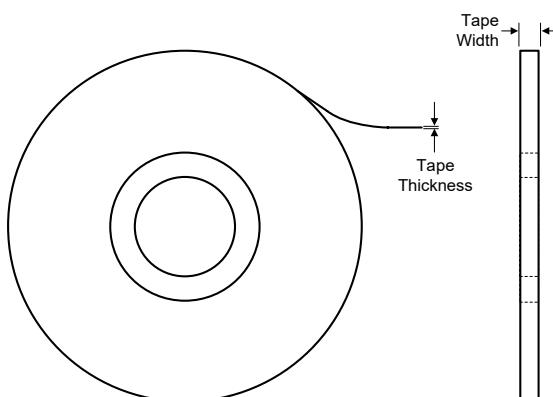
Carrier Tape Dimensions



Dimension	mm		
	Min.	Typ.	Max.
A	176	178	180
C	13.2	13.4	13.6
W1	12	13	15
W2	14.5	15.5	17.5

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Cover Tape Dimensions



Dimension	mm		
	Min.	Typ.	Max.
A0	5.20	5.25	5.30
B0	5.20	5.25	5.30
K0	1.00	1.10	1.20
P0	3.80	4.00	4.20
P1	7.90	8.00	8.10
P2	1.95	2.00	2.05
D0	1.50	1.55	1.60
D1	1.50	-	-
E	1.65	1.75	1.85
F	5.45	5.50	5.55
10P0	39.80	40.00	40.20
W	11.90	12.00	12.30
T	0.25	0.30	0.35
θ	0°		5°
θ2	0°		5°

DWG-0300-01

Dimensions	Dimension	mm		
		Min.	Typ.	Max.
	Tape Thickness	0.043	0.048	0.053
8mm	Tape Width	9.2	9.3	9.4

DWG-0301-01

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